BQ25606 Standalone 3.0-A Single Cell Battery Charger

1 Features

- High-efficiency, 1.5-MHz, synchronous switch-mode buck charger
  - 92% Charge efficiency at 2-A from 5-V input
  - Optimized for USB voltage input (5 V)
- Supports USB On-The-Go (OTG)
  - Boost converter with up to 1.2-A output
  - 92% Boost efficiency at 1-A output
  - Accurate constant current (CC) limit
  - Soft-start up to 500-µF capacitive load
  - Output short circuit protection
- Single input to support USB input and high voltage adapters
  - Support 3.9-V to 13.5-V input voltage range with 22-V absolute maximum input voltage rating
  - Maximum power tracking by input voltage limit up to 4.6 V (VINDPM)
  - VINDPM Threshold automatically tracks battery voltage
  - Auto detect USB SDP, DCP and non-standard adaptors
- High battery discharge efficiency with 19.5-mΩ battery discharge MOSFET
- Narrow VDC (NVDC) power path management
  - Instant-on works with no battery or deeply discharged battery
  - Ideal diode operation in battery supplement mode
- High integration includes all MOSFETs, current sensing and loop compensation
- 58-µA Low battery leakage current with system voltage standby
- High accuracy
  - ±0.5% Charge voltage regulation
  - ±6% at 1.2-A and 1.8-A Charge current regulation
  - ±5% at 0.5-A, 1.2-A and 1.8-A Input current regulation
- Create a Custom Design Using the BQ25606 With the WEBENCH® Power Designer

2 Applications

- EPOS, Portable speakers
- Portable internet devices and accessory

3 Description

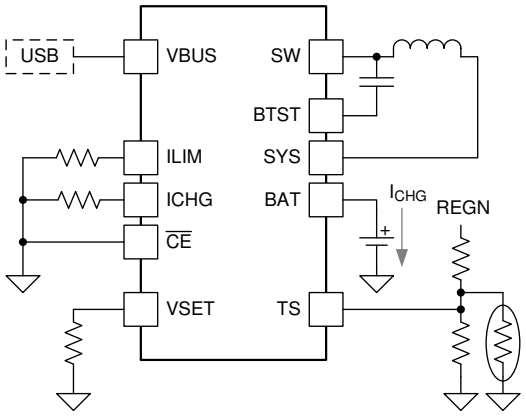
The BQ25606 device is a highly-integrated standalone 3.0-A switch-mode battery charge management and system power path management device for single cell Li-Ion and Li-polymer battery. The low impedance power path optimizes switch-mode operation efficiency, reduces battery charging time and extends battery life during discharging phase.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
BQ25606	VQFN (24)	4.00 mm × 4.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Application



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (August 2017) to Revision B **Page**

- Changed Application section ... 1

Changes from Original (May 2017) to Revision A **Page**

- Updated data sheet title ... 1
- Deleted 200 nS Fast Turn-Off in *Features* ... 1
- Updated *Simplified Application* schematic ... 1
- Changed ACDRV pin references to "NC" in *Pin Configuration and Functions* section ... 4
- Deleted ACDRV pin references from *Pin Functions* table ... 4
- Updated VAC pin description in *Pin Functions* table ... 5
- Deleted ACDRV pin references from *Absolute Maximum Ratings* table ... 6
- Added *ESD Ratings* table ... 6
- Deleted VAC debounce time from*Timing Requirements* table ... 7
- Updated *Functional Block Diagram* ... 16
- Updated *Power Up from Input Source* section ... 17
- Deleted *Power Up OVPFET* section ... 17
- Deleted *OVPFET Startup Control* timing illustration ... 17
- Updated *Input Overvoltage (ACOV)* section ... 21
- Updated *BQ25606 Application Diagram* schematic ... 24

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5 Description (continued)

The BQ25606 is a highly-integrated standalone 3.0-A switch-mode battery charge management and system power path management device for single cell Li-Ion and Li-polymer battery. It features fast charging with high input voltage support for a wide range of standalone chargers and portable devices. Its low impedance power path optimizes switch-mode operation efficiency, reduces battery charging time and extends battery life during discharging phase. Its input voltage and current regulation deliver maximum charging power to battery. The solution is highly integrated with input reverse-blocking FET (RBFET, Q1), high-side switching FET (HSFET, Q2), low-side switching FET (LSFET, Q3), and battery FET (BATFET, Q4) between system and battery. It also integrates the bootstrap diode for the high-side gate drive for simplified system design.

The device supports a wide range of input sources, including standard USB host port, USB charging port, and USB compliant high voltage adapter. The device sets default input current limit based on the built-in USB interface. The device is compliant with USB 2.0 and USB 3.0 power spec with input current and voltage regulation. When the device built-in USB interface identifies the input adaptor is unknown, the device's input current limit is determined by the ILIM pin setting resistor value. The device also meets USB On-the-Go (OTG) operation power rating specification by supplying 5.15 V on VBUS with constant current limit up to 1.2A.

The power path management regulates the system slightly above battery voltage but does not drop below 3.5 V minimum system voltage. With this feature, the system maintains operation even when the battery is completely depleted or removed. When the input current limit or voltage limit is reached, the power path management automatically reduces the charge current to zero. As the system load continues to increase, the power path discharges the battery until the system power requirement is met. This Supplement Mode prevents overloading the input source.

The device initiates and completes a charging cycle without software control. It senses the battery voltage and charges the battery in three phases: pre-conditioning, constant current and constant voltage. At the end of the charging cycle, the charger automatically terminates when the charge current is below a preset limit and the battery voltage is higher than recharge threshold. If the fully charged battery falls below the recharge threshold, the charger automatically starts another charging cycle.

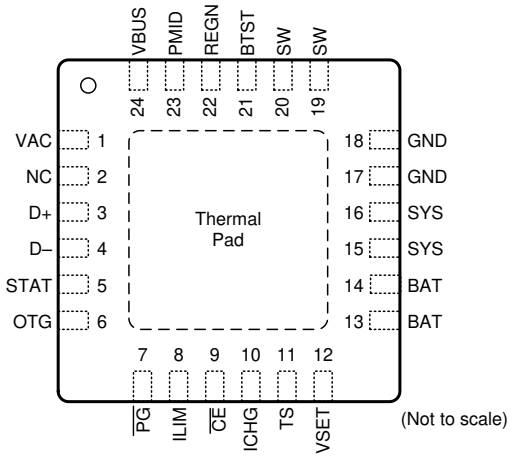
The charger provides various safety features for battery charging and system operations, including battery negative temperature coefficient thermistor monitoring, charging safety timer and overvoltage and overcurrent protections. The thermal regulation reduces charge current when the junction temperature exceeds 110°C. The STAT output reports the charging status and any fault conditions. Other safety features include battery temperature sensing for charge and boost mode, thermal regulation and thermal shutdown and input UVLO and overvoltage protection.

The device family is available in 24-pin, 4 mm x 4 mm QFN package.

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6 Pin Configuration and Functions

BQ25606 WQFN Package
24-Pin WQFN
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
NC	2		No connection. This pin must be floating.
BAT	13	P	Battery connection point to the positive terminal of the battery pack. The internal current sensing resistor is connected between SYS and BAT. Connect a 10 µF closely to the BAT pin.
	14		
BTST	21	P	PWM high side driver positive supply. internally, the BTST is connected to the cathode of the boost-strap diode. Connect the 0.047-µF bootstrap capacitor from SW to BTST.
$\overline{CE}$	9	DI	Charge enable pin. When this pin is driven low, battery charging is enabled.
D+	3	AIO	Positive line of the USB data line pair. D+/D– based USB host/charging port detection. The detection includes data contact detection (DCD), primary and secondary detection in BC1.2 and nonstandard adaptors
D–	4	AIO	Negative line of the USB data line pair. D+/D– based USB host/charging port detection. The detection includes data contact detection (DCD), primary and secondary detection in BC1.2 and nonstandard adaptors
GND	17	P	Power ground and signal ground
	18		
ICHG	10	AI	I_{CHG} pin sets the charge current limit. A resistor is connected from I_{CHG} pin to ground to set charge current limit as $I_{CHG} = K_{ICHG}/R_{ICHG}$. The acceptable range for charge current is 300 mA – 3000 mA.
ILIM	8	AI	ILIM sets the input current limit. A resistor is connected from ILIM pin to ground to set the input current limit as IINDPM = K_{ILIM}/R_{ILIM}. The acceptable range for ILIM current is 500 mA - 3200 mA. The resistor based input current limit is effective only when the input adapter is detected as unknown. Otherwise, the input current limit is determined by D+/D– detection outcome.
OTG	6	DI	Boost mode enable pin. When this pin is pulled HIGH, OTG is enabled. OTG cannot be floating.
$\overline{PG}$	7	DO	Open drain active low power good indicator. Connect to the pull up rail through 10 kΩ resistor. LOW indicates a good input if the input voltage is between UVLO and ACOV, above SLEEP mode threshold, and input current limit is above 30 mA.
PMID	23	P	Connected to the drain of the reverse blocking MOSFET (RBFET) and the drain of HSFET. Put a 10 -µF ceramic capacitor between PMID and GND.
REGN	22	P	PWM low side driver positive supply output. Internally, REGN is connected to the anode of the boost-strap diode. Connect a 4.7-µF (10-V rating) ceramic capacitor from REGN to analog GND. The capacitor should be placed close to the IC.

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Pin Functions (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
STAT	5	DO	Open-drain interrupt output. Connect the STAT pin to a logic rail via 10-kΩ resistor. The STAT pin indicates charger status. Charge in progress: LOW Charge complete or charger in SLEEP mode: HIGH Charge suspend (fault response): BlinK at 1Hz
SW	19	P	Switching node connecting to output inductor. Internally SW is connected to the source of the n-channel HSFET and the drain of the n-channel LSFET. Connect the 0.047-μF bootstrap capacitor from SW to BTST.
	20		
SYS	15	P	Converter output connection point. The internal current sensing resistor is connected between SYS and BAT. Connect a 20 μF capacitor close to the SYS pin.
	16		
TS	11	AI	Temperature qualification voltage input to support JEITA profile. Connect a negative temperature coefficient thermistor. Program temperature window with a resistor divider from REGN to TS to GND. Charge suspends when TS pin voltage is out of range. Recommend 103AT-2 thermistor.
VAC	1	AI	Input voltage sensing. This pin must be shorted to VBUS pin.
VBUS	24	P	Charger input voltage. The internal n-channel reverse block MOSFET (RBFET) is connected between VBUS and PMID with VBUS on source. Place a 1-uF ceramic capacitor from VBUS to GND and place it as close as possible to IC.
VSET	12	AI	VSET pin sets default battery charge voltage in BQ25606. Program battery regulation voltage with a resistor pull-down from VSET to GND. R_{PD} > 50kΩ (float pin) = 4.208 V R_{PD} < 500Ω (short to GND) = 4.352 V 5kΩ < R_{PD} < 25kΩ = 4.400 V
Thermal Pad		P	Ground reference for the device that is also the thermal pad used to conduct heat from the device. This connection serves two purposes. The first purpose is to provide an electrical ground connection for the device. The second purpose is to provide a low thermal-impedance path from the device die to the PCB. This pad should be tied externally to a ground plane.

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7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Voltage Range (with respect to GND)	VAC	–2	22	V
Voltage Range (with respect to GND)	VBUS (converter not switching)(2)	–2	22	V
Voltage Range (with respect to GND)	BTST, PMID (converter not switching)(2)	–0.3	22	V
Voltage Range (with respect to GND)	SW	–2	16	V
Voltage Range (with respect to GND)	BTST to SW	–0.3	7	V
Voltage Range (with respect to GND)	D+, D–	–0.3	7	V
Voltage Range (with respect to GND)	REGN, TS, $\overline{CE}$, $\overline{PG}$, BAT, SYS (converter not switching)	–0.3	7	V
Output Sink Current	STAT		6	mA
Voltage Range (with respect to GND)	VSET, ILIM, ICHG, OTG	–0.3	7	V
Voltage Range (with respect to GND)	PGND to GND (QFN package only)	–0.3	0.3	V
Operating junction temperature, T_J		–40	150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under Absolute maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. All voltage values are with respect to the network ground terminal unless otherwise noted.
(2) VBUS is specified up to 22 V for a maximum of one hour at room temperature

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±250	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V_{BUS}	Input voltage	3.9		13.5(1)	V
I_{in}	Input current (VBUS)			3.25	A
I_{SYSOP}	Output current (SW)			3.0	A
V_{BATOP}	Battery voltage			4.4	V
I_{BATOP}	Fast charging current			3.0	A
I_{BATOP}	Discharging current (continuous)			6	A
T_A	Operating ambient temperature	–40		85	°C

(1) The inherent switching noise voltage spikes should not exceed the absolute maximum voltage rating on either the BTST or SW pins. A tight layout minimizes switching noise.

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7.4 Thermal Information

THERMAL METRIC		BQ25606 RGE (VQFN) 24 Pins	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	31.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	27	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	9.2	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	9.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	2.8	°C/W

7.5 Timing Requirements

Parameter		Additional infor mAtion	Min	NOM	mAX	UNIT
VBUS/BAT POWER UP						
t_{ACOV}	VBUS OVP reaction time	VAC rising above ACOV threshold to turn off Q2		200		ns
t_{BADSRC}	Bad adapter detection duration			30		ms
t_{TERM_DGL}	Deglitch time for charge termination			250		ms
t_{RECHG_DGL}	Deglitch time for recharge			250		ms
$t_{SYSOVLD_DGL}$	System over-current deglitch time to turn off Q4			100		µs
t_{BATOVP}	Battery overvoltage deglitch time to disable charge			1		µs
t_{SAFETY}	Typical Charge Safety Timer Range		8	10	12	hr

7.6 Electrical Characteristics

$V_{VAC_PRESENT} < V_{VAC} < V_{VAC_OV}$ and $V_{VAC} > V_{BAT} + V_{SLEEP}$, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
QUIESCENT CURRENTS						
I_{BAT}	Battery discharge current (BAT, SW, SYS) in buck mode	V_{BAT} = 4.5 V, $V_{BUS} < V_{AC\text{-}UVLOZ}$, leakage between BAT and VBUS, T_J< 85°C			5	µA
I_{BAT}	Battery discharge current (BAT, SW, SYS)	V_{BAT} = 4.5 V, No VBUS, T_J < 85°C		58	85	µA
I_{VBUS}	Input supply current (VBUS) in buck mode	V_{VBUS} = 12 V, $V_{VBUS} > V_{VBAT}$, converter not switching		1.5	3	mA
I_{VBUS}	Input supply current (VBUS) in buck mode	V_{VBUS} > VUVLO, $V_{VBUS} > V_{VBAT}$, converter switching, VBAT = 3.8V, ISYS = 0A		3		mA
I_{BOOST}	Battery discharge current in boost mode	V_{BAT} = 4.2 V, boost mode, I_{VBUS} = 0 A, converter switching		3		mA
VBUS, VAC AND BAT PIN POWER-UP						
V_{BUS_OP}	VBUS operating range	V_{VBUS} rising	3.9		13.5	V
$V_{VAC_PRESENT}$	REGN turn-on threshold	V_{VAC} rising	3.36	3.65	3.97	V
$V_{VAC_PRESENT_HYS}$		V_{VAC} falling		300		mV
V_{SLEEP}	Sleep mode falling threshold	(V_{VAC}–V_{VBAT}), $V_{BUSMIN_FALL} \le V_{BAT} \le V_{REG}$, VAC falling	37	76	126	mV
V_{SLEEPZ}	Sleep mode rising threshold	(V_{VAC}–V_{VBAT}), $V_{BUSMIN_FALL} \le V_{BAT} \le V_{REG}$, VAC rising	130	220	350	mV
$V_{VAC_OV_RISE}$	VAC Overvoltage rising threshold	VAC rising	13.5	14.28	14.91	V
$V_{VAC_OV_HYS}$	VAC Overvoltage hysteresis	VAC falling		520		mV

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Electrical Characteristics (continued)

$V_{VAC_PRESENT} < V_{VAC} < V_{VAC_OV}$ and $V_{VAC} > V_{BAT} + V_{SLEEP}$, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{BAT_DPL_FALL}$	Battery depletion falling threshold (Q4 turn-off threshold)	V_{BAT} falling	2.15		2.6	V
$V_{BAT_DPL_RISE}$	Battery Depletion rising threshold (Q4 turn-on threshold)	V_{BAT} rising	2.35		2.82	V
$V_{BAT_DPL_HYST}$	Battery Depletion rising hysteresis	V_{BAT} rising		180		mV
V_{BUSMIN_FALL}	Bad adapter detection falling threshold	V_{BUS} falling	3.65	3.8	3.93	V
V_{BUSMIN_HYST}	Bad adapter detection hysteresis			200		mV
I_{BADSRC}	Bad adapter detection current source	Sink current from VBUS to GND		30		mA
POWER-PATH						
V_{SYS_MIN}	System regulation voltage	$V_{VBAT} < V_{SYS_MIN\ =\ 3.5V}$, charge enabled or disabled	3.5	3.68		V
V_{SYS}	System regulation voltage	I_{SYS} = 0 A, $V_{VBAT} > V_{SYSMIN}$, charge disabled		V_{BAT} + 50 mV		V
$R_{ON(RBFET)}$	Top reverse blocking MOSFET on-resistance between VBUS and PMID - Q1	-40°C≤ T_A ≤ 125°C		45		mΩ
$R_{ON(HSFET)}$	Top switching MOSFET on-resistance between PMID and SW - Q2	V_{REGN} = 5 V , -40°C≤ T_A ≤ 125°C		62		mΩ
$R_{ON(LSFET)}$	Bottom switching MOSFET on-resistance between SW and GND - Q3	V_{REGN} = 5 V , -40°C≤ T_A ≤ 125°C		70		mΩ
V_{FWD}	BATFET forward voltage in supplement mode			30		mV
$R_{ON(BAT-SYS)}$	SYS-BAT MOSFET on-resistance	QFN package, Measured from BAT to SYS, V_{BAT} = 4.2V, T_J = 25°C		19.5	24	mΩ
$R_{ON(BAT-SYS)}$	SYS-BAT MOSFET on-resistance	QFN package, Measured from BAT to SYS, V_{BAT} = 4.2V, T_J = –40 - 125°C		19.5	30	mΩ
BATTERY CHARGER						
V_{BATREG}	Charge voltage	R_{VSET} > 50 kΩ, –40 ≤ T_J ≤ 85°C	4.187	4.208	4.229	V
		R_{VSET} < 500 Ω, –40 ≤ T_J ≤ 85°C	4.330	4.352	4.374	V
		R_{VSET} = 10 kΩ, –40 ≤ T_J ≤ 85°C	4.378	4.4	4.422	V
V_{BATREG_ACC}	Charge voltage setting accuracy	V_{BAT} = 4.208 V or V_{BAT} = 4.352 V, –40 ≤ T_J ≤ 85°C	–0.5%		0.5%	
$I_{CHG_REG_RANGE}$	Charge current regulation range		0		3000	mA
I_{CHG_REG}	Charge current regulation	R_{ICHG} = 1100 Ω, V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	516	615	715	mA
$I_{CHG_REG_ACC}$	Charge current regulation accuracy	R_{ICHG} = 1100 Ω, V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	-16%		16%	
I_{CHG_REG}	Charge current regulation	R_{ICHG} = 562 Ω, V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	1.14	1.218	1.28	A
I_{CHG_REG}	Charge current regulation accuracy	R_{ICHG} = 562 Ω, V_{BAT} = 3.1 V or V_{BAT} = 3.8 V	-6%		6%	
I_{CHG_REG}	Charge current regulation	R_{ICHG} = 372 Ω, V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	1.715	1.813	1.89	A
$I_{CHG_REG_ACC}$	Charge current regulation accuracy	R_{ICHG} = 372 Ω, V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	-5%		5%	
K_{ICHG}	Charge current regulation setting ratio	R_{ICHG} = 372 Ω, 562 Ω V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	639	677	715	A×Ω
K_{ICHG_ACC}	Charge current regulation setting ratio accuracy	R_{ICHG} = 372Ω, 562 Ω V_{VBAT} = 3.1 V or V_{VBAT} = 3.8 V	-6%		6%	
$V_{BATLOWV_FALL}$	Battery LOWV falling threshold	Fast charge to precharge	2.67	2.8	2.87	V

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Electrical Characteristics (continued)

$V_{VAC_PRESENT} < V_{VAC} < V_{VAC_OV}$ and $V_{VAC} > V_{BAT} + V_{SLEEP}$, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{BATLOWV_RISE}$	Battery LOWV rising threshold	Pre-charge to fast charge	3.0	3.1	3.24	V
I_{PRECHG}	Precharge current regulation	R_{ICHG} = 1100 Ω, V_{VBAT} = 2.6 V, I_{PRECHG} = 5% of I_{CHG} = 615mA	21		38	mA
I_{PRECHG_ACC}	Precharge current regulation accuracy	Percentage of I_{CHG},R_{ICHG} = 1100 Ω, V_{VBAT} = 2.6 V, I_{CHG} = 615mA	3.4%		6.2%	
I_{PRECHG}	Precharge current regulation	R_{ICHG} = 562 Ω, V_{VBAT} = 2.6 V, I_{PRECHG} = 5% of I_{CHG} = 1.218A	48		67	mA
I_{PRECHG_ACC}	Precharge current regulation accuracy	Percentage of I_{CHG},R_{ICHG} = 562 Ω, V1330 = 2.6 V, I_{CHG} = 1.218A	3.9%		5.5%	
I_{PRECHG}	Precharge current regulation	R_{ICHG} = 372 Ω, V_{VBAT} = 2.6 V, I_{PRECHG} = 5% of I_{CHG} = 1.813A	76		97	mA
I_{PRECHG_ACC}	Precharge current regulation accuracy	Percentage of I_{CHG},R_{ICHG} = 372 Ω, V_{VBAT} = 2.6 V, I_{CHG} = 1.813A	4.1%		5.4%	
I_{TERM}	Termination current regulation	R_{ICHG} = 562 Ω, V_{VBAT} = 4.35V, $_{CHG}$ = 1.218A	26		100	mA
I_{TERM_ACC}	Termination current regulation accuracy	Percentage of I_{CHG}, R_{ICHG} = 562 Ω, V_{VBAT} = 4.35 V, I_{CHG} = 1.218 A	2.1%		8.3%	
I_{TERM}	Termination current regulation	R_{ICHG} = 372 Ω, V_{VBAT} = 4.35 V, I_{CHG} = 1.813 A	56	100	126	mA
I_{TERM_ACC}	Termination current regulation accuracy	Percentage of I_{CHG}, R_{ICHG} = 372 Ω, V_{VBAT} = 4.35 V, I_{CHG} = 1.813 A	3.0%		7.0%	
V_{SHORT}	Battery short voltage	V_{VBAT} falling	1.85	2	2.15	V
V_{SHORTZ}	Battery short voltage	V_{VBAT} rising	2.05	2.25	2.35	V
I_{SHORT}	Battery short current	$V_{VBAT} < V_{SHORTZ}$	70	90	110	mA
V_{RECHG}	Recharge Threshold below V_{BAT_REG}	V_{BAT} falling	87	121	156	mV
$I_{SYSLOAD}$	System discharge load current	V_{SYS} = 4.2 V		30		mA
INPUT VOLTAGE AND CURRENT REGULATION						
V_{DPM_VBAT}	Input voltage regulation limit	V_{VBAT} < 4.1 V (V_{VBAT}= 3.6 V)	4.171	4.3	4.429	V
$V_{DPM_VBAT_ACC}$	Input voltage regulation accuracy	V_{VBAT} < 4.1 V (V_{VBAT} = 3.6 V)	–3%		3%	
I_{INDPM}	USB input current regulation limit	V_{VBUS} = 5 V, USB500 charge port detected by DPDM , –40 ≤ T_J ≤ 85°C	448		500	mA
I_{INDPM}	Input current regulation limit	R_{ILIM} = 910 Ω, unknown adaptor detected by DPDM , –40 ≤ T_J ≤ 85°C	505	526	550	mA
I_{INDPM}	Input current regulation limit accuracy	R_{ILIM} = 374 Ω, unknown adaptor detected by DPDM , –40 ≤ T_J ≤ 85°C	1220	1276	1330	mA
I_{INDPM}	Input current regulation limit	R_{ILIM} = 265 Ω, unknown adaptor detected by DPDM , –40 ≤ T_J ≤ 85°C	1.73	1.8	1.871	A
I_{INDPM_ACC}	Input current regulation limit accuracy	R_{ILIM} = 265 Ω, 374 Ω, 910 Ω, unknown adaptor detected by DPDM , –40 ≤ T_J ≤ 85°C	–5%		5%	
K_{ILIM}	Input current setting ratio, I_{LIM} = K_{ILIM} / R_{ILIM}	R_{ILIM} = 910 Ω, 374 Ω, 265 Ω, unknown adaptor detected by DPDM, –40 ≤ T_J ≤ 85°C	459	478	500	A×Ω
K_{ILIM_ACC}	Input current setting ratio, I_{LIM} = K_{ILIM} / R_{ILIM}	R_{ILIM} = 910 Ω, 374 Ω, 265 Ω, unknown adaptor detected by DPDM, –40 ≤ T_J ≤ 85°C	–5%		5%	
I_{IN_START}	Input current limit during system start-up sequence			200		mA

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Electrical Characteristics (continued)

$V_{VAC_PRESENT}$ < V_{VAC} < V_{VAC_OV} and V_{VAC} > V_{BAT} + V_{SLEEP}, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BAT PIN OVERVOLTAGE PROTECTION						
V_{BATOVP_RISE}	Battery overvoltage threshold	V_{BAT} rising, as percentage of V_{BAT_REG}	103%	104%	105%	
V_{BATOVP_FALL}	Battery overvoltage threshold	V_{BAT} falling, as percentage of V_{BAT_REG}	101%	102%	103%	

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Electrical Characteristics (continued)

$V_{VAC_PRESENT} < V_{VAC} < V_{VAC_OV}$ and $V_{VAC} > V_{BAT} + V_{SLEEP}$, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
THERMAL REGULATION AND THERMAL SHUTDOWN						
$T_{JUNCTION_REG}$	Junction Temperature Regulation Threshold			110		°C
T_{SHUT}	Thermal Shutdown Rising Temperature	Temperature Increasing		160		°C
T_{SHUT_HYST}	Thermal Shutdown Hysteresis			30		°C
JEITA Thermistor Comparator (BUCK MODE)						
V_{T1}	T1 (0°C) threshold, Charge suspended T1 below this temperature.	Charger suspends charge. As Percentage to V_{REGN}	72.4%	73.3%	74.2%	
V_{T1}	Falling	As Percentage to V_{REGN}	69%	71.5%	74%	
V_{T2}	T2 (10°C) threshold, Charge back to I_{CHG}/2 and 4.2 V below this temperature	As percentage of V_{REGN}	67.2%	68%	69%	
V_{T2}	Falling	As Percentage to V_{REGN}	66%	66.8%	67.7%	
V_{T3}	T3 (45°C) threshold, charge back to ICHG and 4.05V above this temperature.	Charger suspends charge. As Percentage to V_{REGN}	43.8%	44.7%	45.8%	
V_{T3}	Falling	As Percentage to V_{REGN}	45.1%	45.7%	46.2%	
V_{T5}	T5 (60°C) threshold, charge suspended above this temperature.	As Percentage to V_{REGN}	33.7%	34.2%	35.1%	
V_{T5}	Falling	As Percentage to V_{REGN}	34.5%	35.3%	36.2%	
COLD OR HOT THERMISTER COMPARATOR (BOOST MODE)						
V_{BCOLD}	Cold Temperature Threshold, TS pin Voltage Rising Threshold	As Percentage to V_{REGN} (Approx. –20°C w/ 103AT), –20°C ≤ T_J≤ 125°C	79.5%	80%	80.5%	
V_{BCOLD}	Falling	–20°C ≤ T_J≤ 125°C	78.5%	79%	79.5%	
V_{BHOT}	Hot Temperature Threshold, TS pin Voltage falling Threshold	As Percentage to V_{REGN} (Approx. 60°C w/ 103AT), –20°C ≤ T_J≤ 125°C	30.2%	31.2%	32.2%	
V_{BHOT}	Rising	–20°C ≤ T_J≤ 125°C	33.8%	34.4%	34.9%	

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Electrical Characteristics (continued)

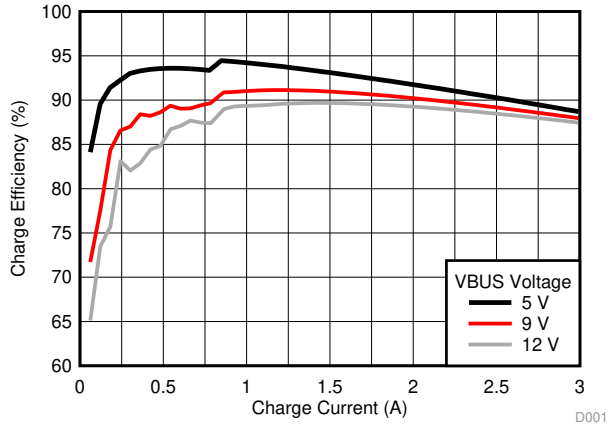
$V_{VAC_PRESENT} < V_{VAC} < V_{VAC_OV}$ and $V_{VAC} > V_{BAT} + V_{SLEEP}$, T_J = –40°C to 125°C and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
CHARGE OVERCURRENT COMPARATOR (CYCLE-BY-CYCLE)						
I_{HSFET_OCP}	HSFET cycle-by-cycle over-current threshold		5.2		8.0	A
I_{BATFET_OCP}	System over load threshold		6.0			A
PWM						
f_{SW}	PWM switching frequency	Oscillator frequency, buck mode	1320	1500	1680	kHz
		Oscillator frequency, boost mode	1170	1412	1500	kHz
D_{MAX}	Maximum PWM duty cycle(1)			97%		
BOOST MODE OPERATION						
V_{OTG_REG}	Boost mode regulation voltage	V_{VBAT} = 3.8 V, $I_{(PMID)}$ = 0 A	4.972	5.126	5.280	V
$V_{OTG_REG_ACC}$	Boost mode regulation voltage accuracy	V_{VBAT} = 3.8 V, $I_{(PMID)}$ = 0 A	-3		3	%
$V_{BATLOWV_OTG}$	Battery voltage exiting boost mode	V_{VBAT} falling	2.6	2.8	2.9	V
	Battery voltage entering boost mode	V_{VBAT} rising	2.9	3.0	3.15	V
I_{OTG}	OTG mode output current limit		1.2	1.4	1.6	A
V_{OTG_OVP}	OTG overvoltage threshold	Rising threshold	5.55	5.8	6.15	V
REGN LDO						
V_{REGN}	REGN LDO output voltage	V_{VBUS} = 9 V, I_{REGN} = 40 mA	5.6	6	6.65	V
V_{REGN}	REGN LDO output voltage	V_{VBUS} = 5 V, I_{REGN} = 20 mA	4.6	4.7	4.9	V
LOGIC I/O PIN CHARACTERISTICS ($\overline{CE}$, PSEL, SCL, SDA,, $\overline{INT}$)						
V_{ILO}	Input low threshold $\overline{CE}$				0.4	V
V_{IH}	Input high threshold $\overline{CE}$		1.3			V
I_{BIAS}	High-level leakage current $\overline{CE}$	Pull up rail 1.8 V			1	µA
V_{ILO}	Input low threshold OTG				0.4	V
V_{IH}	Input high threshold OTG		1.3			V
I_{BIAS}	High-level leakage current OTG	Pull up rail 1.8 V			1	µA
LOGIC I/O PIN CHARACTERISTICS ($\overline{PG}$, STAT)						
V_{OL}	Low-level output voltage				0.4	V
D+/D– DETECTION						
V_{D+_1P2}	D+ Threshold for Non-standard adapter (combined V1P2_VTH_LO and V1P2_VTH_HI)		1.05		1.35	V
I_{D+_LKG}	Leakage current into D+	HiZ	-1		1	µA
$V_{D-_600MVSRC}$	Voltage source (600 mV)		500	600	700	mV
$I_{D-_100UAISNK}$	D– current sink (100 µA)	V_{D-} = 500 mV,	50	100	150	µA
R_{D-_19K}	D– resistor to ground (19 kΩ)	V_{D-} = 500 mV,	14.25		24.8	kΩ
V_{D-_0P325}	D– comparator threshold for primary detection	D– pin Rising	250		400	mV
V_{D-_2P8}	D– Threshold for non-standard adapter (combined V2P8_VTH_LO and V2P8_VTH_HI)		2.55		2.85	V
V_{D-_2P0}	D– Comparator threshold for non-standard adapter (For non-standard – same as bq2589x)		1.85		2.15	V
V_{D-_1P2}	D– Threshold for non-standard adapter (combined V1P2_VTH_LO and V1P2_VTH_HI)		1.05		1.35	V
I_{D-_LKG}	Leakage current into D–	HiZ	-1		1	µA

(1) Specified by design. Not production tested.

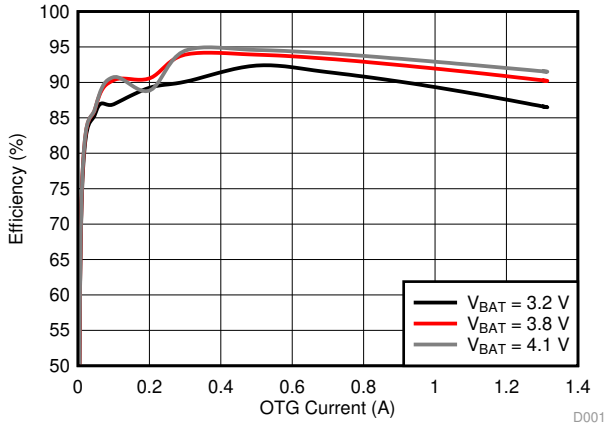
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7.7 Typical Characteristics



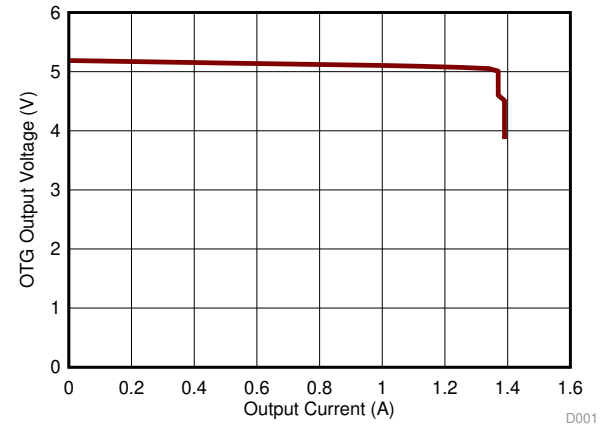
f_{SW} = 1.5 MHz Inductor DCR = 18 mΩ
V_{BAT} = 3.8 V

Figure 1. Charge Efficiency vs. Charge Current



V_{OTG} = 5.15 V inductor DCR = 18 mΩ

Figure 2. Efficiency vs. OTG Current



0 A ≤ I_{OTG} ≤1.37 A V_{OTG} = 5.15 V
V_{VBAT} = 3.8 V

Figure 3. OTG Output Voltage vs. Output Current

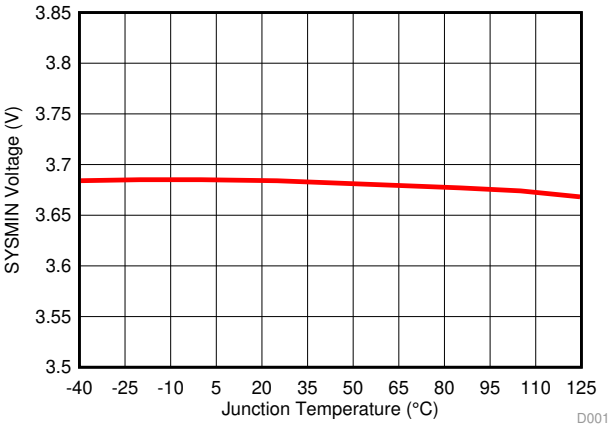


Figure 4. SYSMIN Voltage vs. Junction Temperature

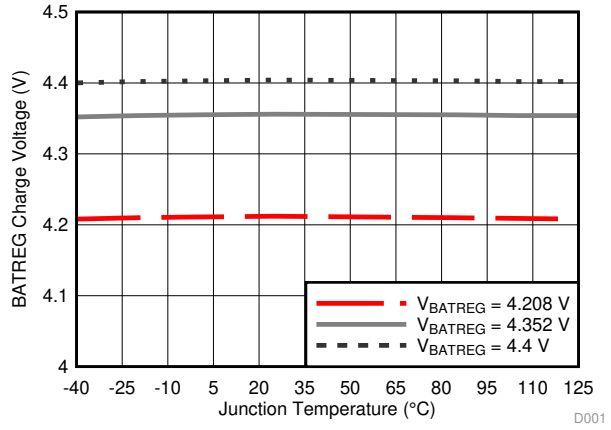
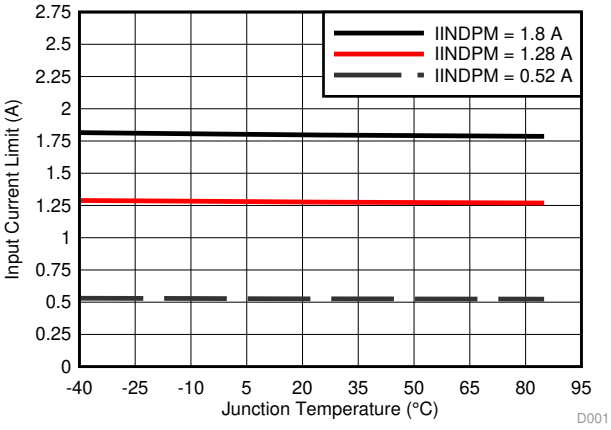


Figure 5. BATREG Charge Voltage vs. Junction Temperature

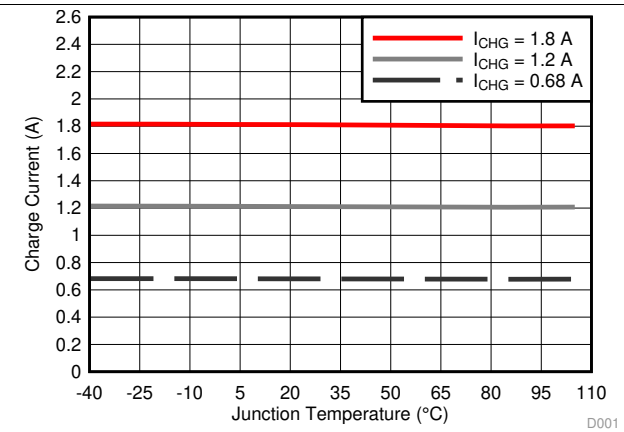


V_{VBUS} = 5 V

Figure 6. Input Current Limit vs. Junction Temperature

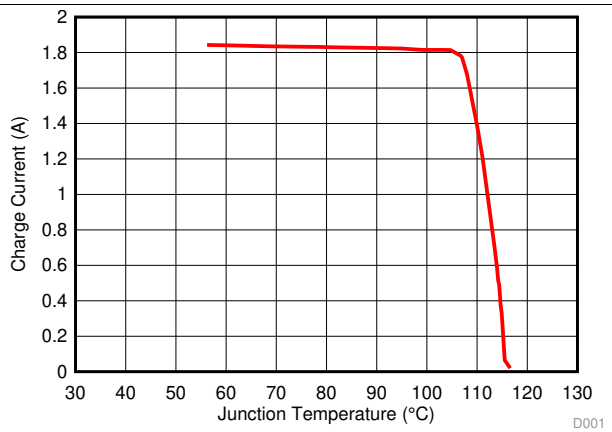
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Typical Characteristics (continued)



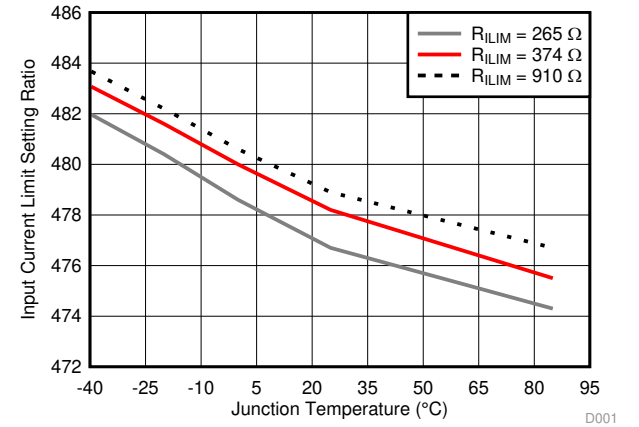
V_{VBUS} = 5 V V_{BAT} = 3.8 V

Figure 7. Charge Current vs. Junction Temperature



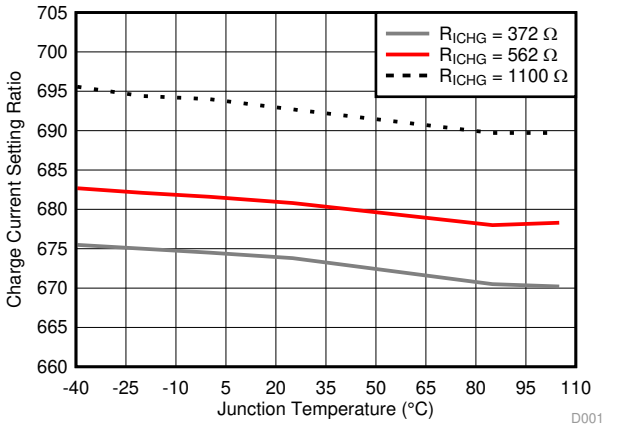
V_{VBUS} = 5V V_{BAT} = 3.8V

Figure 8. Charge Current vs. Junction Temperature Under Thermal Regulation



V_{VBUS} = 5 V V_{BAT} = 3.8 V

Figure 9. Input Current Limit Setting Ratio vs. Junction Temperature



V_{VBUS} = 5 V V_{BAT} = 3.8 V

Figure 10. Charge Current Setting Ratio vs. Junction Temperature

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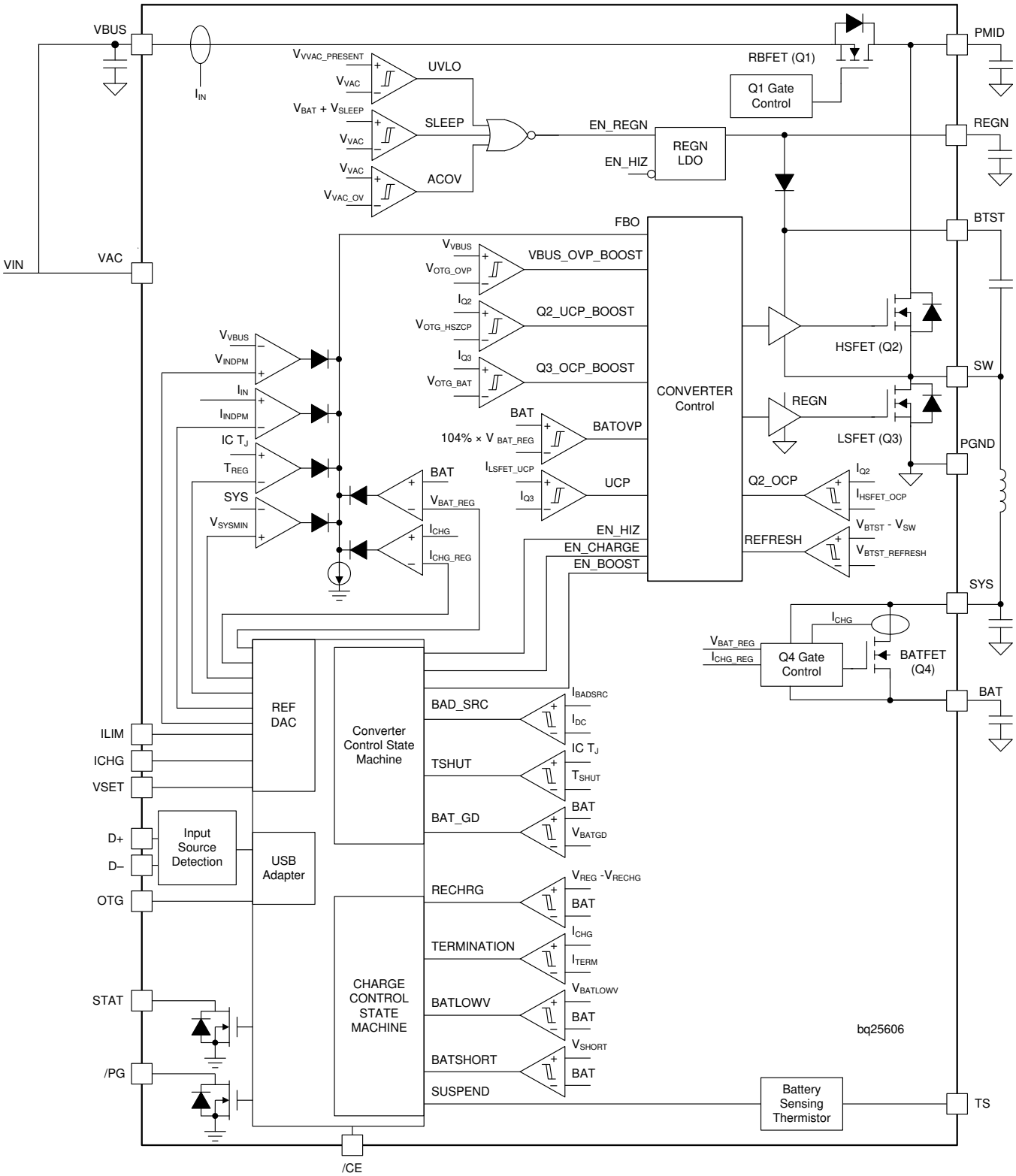
8 Detailed Description

8.1 Overview

The BQ25606 device is a highly integrated 3.0-A switch-mode battery charger for single cell Li-Ion and Li-polymer battery. It includes the input reverse-blocking FET (RBFET, Q1), high-side switching FET (HSFET, Q2), low-side switching FET (LSFET, Q3), and battery FET (BATFET, Q4), and bootstrap diode for the high-side gate drive.

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8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 Device Power Up from Battery without Input Source

If only battery is present and the voltage is above depletion threshold ($V_{BAT_DPL_RISE}$), the BATFET turns on and connects battery to system. The REGN stays off to minimize the quiescent current. The low RDSON of BATFET and the low quiescent current on BAT minimize the conduction loss and maximize the battery run time.

The device always monitors the discharge current through BATFET (*Supplement Mode*). When the system is overloaded or shorted (I_{BAT} > I_{BATFET_OCP}), the device turns off BATFET immediately until the input source plugs in again.

8.3.2 Power Up from Input Source

When an input source is plugged in, the device checks the input source voltage to turn on REGN LDO and all the bias circuits. It detects and sets the input current limit before the buck converter is started. The power up sequence from input source is as listed:

1. Power Up REGN LDO
2. Poor Source Qualification
3. Input Source Type Detection is based on D+/D– to set input current limit (IINDPM) .
4. Input Voltage Limit Threshold Setting (VINDPM threshold)
5. Converter Power-up

8.3.2.1 Power Up REGN Regulation

The REGN LDO supplies internal bias circuits as well as the HSFET and LSFET gate drive. The REGN also provides bias rail to TS external resistors. The pull-up rail of STAT can be connected to REGN as well. The REGN is enabled when all the below conditions are valid:

- V_{VAC} above $V_{VAC_PRESENT}$
- V_{VAC} above V_{BAT} + V_{SLEEPZ} in buck mode or VBUS below V_{BAT} + V_{SLEEP} in boost mode
- After 220-ms delay is completed

If any one of the above conditions is not valid, the device is in high impedance mode (HIZ) with REGN LDO off. The device draws less than IVBUS_HIZ from VBUS during HIZ state. The battery powers up the system when the device is in HIZ.

8.3.2.2 Poor Source Qualification

After REGN LDO powers up, the device confirms the current capability of the input source. The input source must meet both of the following requirements in order to start the buck converter.

- VAC voltage below V_{VAC_OV}
- VBUS voltage above $V_{VBUSMIN}$ when pulling I_{BADSRC} (typical 30 mA)

If the device fails the poor source detection, it repeats poor source qualification every 2 seconds.

8.3.2.3 Input Source Type Detection

After the REGN LDO is powered, the device runs input source detection through D+/D– lines. The BQ25606 follows the USB Battery Charging Specification 1.2 (BC1.2) to detect input source (SDP/ DCP) and non-standard adapter through USB D+/D– lines. The BQ25606 sets input current limit through D+/D- detection and ILIM pins.

8.3.2.3.1 D+/D– Detection Sets Input Current Limit in BQ25606

The BQ25606 contains a D+/D– based input source detection to set the input current limit at VBUS plug-in. The D+/D– detection includes standard USB BC1.2 and non-standard adapter. When input source is plugged in, the device starts standard USB BC1.2 detections. The USB BC1.2 is capable to identify Standard Downstream Port (SDP) and Dedicated Charging Port (DCP). When the Data Contact Detection (DCD) timer expires, the non-standard adapter detection is applied to set the input current limit. The non-standard detection is used to distinguish vendor specific adapters (Apple and Samsung) based on their unique dividers on the D+/D– pins. If an adapter is detected as DCP, the input current limit is set at 2.4 A. If an adapter is detected as unknown, the input current limit is set by ILIM pin.

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Feature Description (continued)

Table 1. Non-Standard Adapter Detection

Non-Standard Adapter	D+ Threshold	D– Threshold	Input Current Limit (A)
Divider 1	V_{D+} within V_{2P7_VTH}	V_{D-} within V_{2P0_VTH}	2.1
Divider 2	V_{D+} within V_{1P2_VTH}	V_{D-} within V_{1P2_VTH}	2
Divider 3	V_{D+} within V_{2P0_VTH}	V_{D-} within V_{2P7_VTH}	1
Divider 4	V_{D+} within V_{2P7_VTH}	V_{D-} within V_{2P7_VTH}	2.4

Table 2. Input Current Limit Setting from D+/D– Detection

D+/D– Detection	Input Current Limit (IINLIM)
USB SDP (USB500)	500 mA
USB DCP	2.4 A
Divider 3	1 A
Divider 1	2.1 A
Divider 4	2.4 A
Divider 2	2 A
Unknown 5-V Adapter	Set by ILIM pin

8.3.2.4 Input Voltage Limit Threshold Setting (VINDPM Threshold)

The device's VINDPM is set at 4.3V. The device supports dynamic VINDPM tracking which tracks the battery voltage. The device's VINDPM tracks battery voltage with 200mV offset such that when VBAT + 200mV is greater than 4.3V, the VINDPM value is automatically adjusted to VBAT + 200mV.

8.3.2.5 Converter Power-Up

After the input current limit is set, the converter is enabled and the HSFET and LSFET start switching. If battery charging is disabled, BATFET turns off. Otherwise, BATFET stays on to charge the battery.

The device provides soft-start when system rail is ramped up. When the system rail is below 2.2 V, the input current is limited to is to 200 mA. After the system rises above 2.2 V, the device limits input current to the value set by ILIM pin.

As a battery charger, the device deploys a highly efficient 1.5 MHz step-down switching regulator. The fixed frequency oscillator keeps tight control of the switching frequency under all conditions of input voltage, battery voltage, charge current and temperature, simplifying output filter design.

The device switches to PFM control at light load or when battery is below minimum system voltage setting or charging is disabled.

8.3.3 Boost Mode Operation From Battery

The device supports boost converter operation to deliver power from the battery to other portable devices through USB port. The maximum output current is up to 1.2 A. The boost operation can be enabled if the conditions are valid:

1. BAT above V_{OTG_BAT}
2. VBUS less than BAT+V_{SLEEP} (in sleep mode)
3. Boost mode operation is enabled (OTG pin HIGH)
4. Voltage at TS (thermistor) pin as a percentage of V_{REGN} is within acceptable range ($V_{BHOT} < V_{TS} < V_{BCOLD}$)
5. After 30-ms delay from boost mode enable

During boost mode, the VBUS output is 5.15 V and the output current can reach up to 1.2 A. The boost output is maintained when BAT is above V_{OTG_BAT} threshold.

When OTG is enabled, the device starts up with PFM and later transits to PWM to minimize the overshoot.

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8.3.4 Standalone Power Management

8.3.5 Power Path Management

The device accommodates a wide range of input sources from USB, wall adapter, to car charger. The device provides automatic power path selection to supply the system (SYS) from input source (VBUS), battery (BAT), or both.

8.3.6 Battery Charging Management

The device charges 1-cell Li-Ion battery with up to 3.0-A charge current for high capacity tablet battery. The 19.5-mΩ BATFET improves charging efficiency and minimize the voltage drop during discharging.

8.3.6.1 Autonomous Charging Cycle

With battery charging is enabled ($\overline{CE}$ pin is LOW), the device autonomously completes a charging cycle. The device default charging parameters are listed in Table 3.

Table 3. Charging Parameter Default Setting

Default Mode	BQ25606
Charging voltage	VSET controlled
Charging current	I_{CHG} controlled
Pre-charge current	5% of ICHG
Termination current	5% of ICHG
Temperature profile	JEITA
Safety timer	10 hours

A new charge cycle starts when the following conditions are valid:

- Converter starts
- Battery charging is enabled ($\overline{CE}$ is low)
- No thermistor fault on TS
- No safety timer fault

The charger device automatically terminates the charging cycle when the charging current is below termination threshold, battery voltage is above recharge threshold, and device not is in DPM mode or thermal regulation. When a fully charged battery is discharged below recharge threshold , the device automatically starts a new charging cycle. After the charge is done, toggle $\overline{CE}$ pin can initiate a new charging cycle.

The STAT output indicates the charging status: charging (LOW), charging complete or charge disable (HIGH) or charging fault (Blinking).

8.3.6.2 Charging Termination

The device terminates a charge cycle when the battery voltage is above recharge threshold, and the current is below termination current. After the charging cycle is completed, the BATFET turns off. The converter keeps running to power the system, and BATFET can turn on again to engage *Supplement Mode*.

8.3.6.3 Thermistor Qualification

The charger device provides a single thermistor input for battery temperature monitor.

8.3.6.4 JEITA Guideline Compliance During Charging Mode

To improve the safety of charging Li-ion batteries, JEITA guideline was released on April 20, 2007. The guideline emphasized the importance of avoiding a high charge current and high charge voltage at certain low and high temperature ranges.

To initiate a charge cycle, the voltage on TS pin must be within the VT1 to VT5 thresholds. If TS voltage exceeds the T1-T5 range, the controller suspends charging and waits until the battery temperature is within the T1 to T5 range.

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At cool temperature (T1-T2), the charge current is reduced to 20% of programmed fast charge current. At warm temperature (T3-T5), the charge voltage is reduced to 4.1 V.

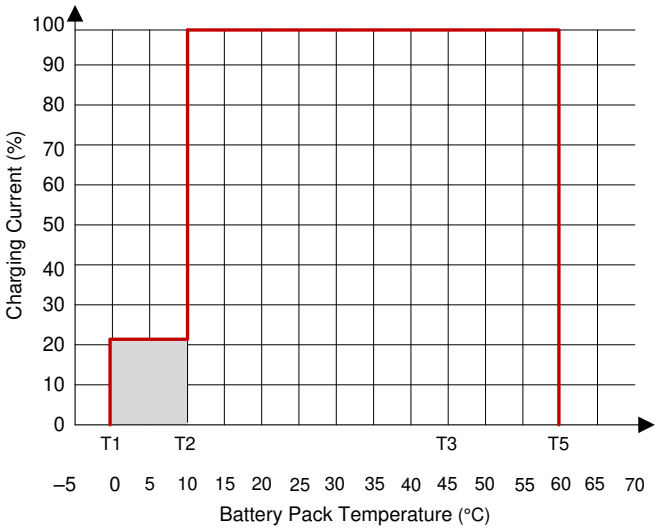


Figure 11. JEITA Profile: Charging Current

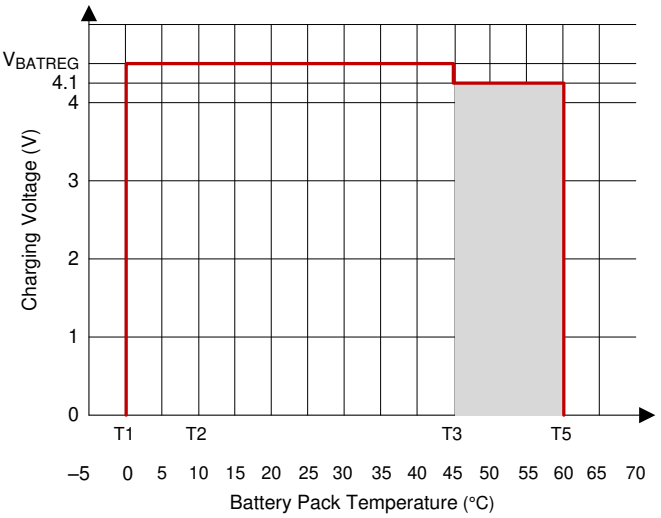


Figure 12. JEITA Profile: Charging Voltage

Equation 1 through Equation 2 describe updates to the resistor bias network.

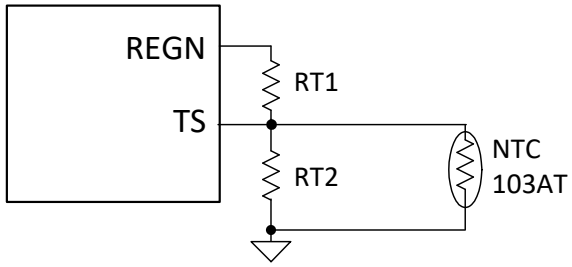


Figure 13. TS Pin Resistor Network

$$RT2 = \frac{R_{NTC,T1} \times R_{NTC,T5} \times \left(\frac{1}{V_{T5}\%} - \frac{1}{V_{T1}\%}\right)}{R_{NTC,T1} \times \left(\frac{1}{V_{T1}\%} - 1\right) - R_{NTC,T5} \times \left(\frac{1}{V_{T5}\%} - 1\right)} \quad (1)$$

$$RT1 = \frac{\frac{1}{V_{T1}\%} - 1}{\frac{1}{R_{T2}} + \frac{1}{R_{NTC,T1}}} \quad (2)$$

Select 0°C to 60°C range for Li-ion or Li-polymer battery:

- RTH_{COLD} = 27.28 KΩ
- RTH_{HOT} = 3.02 KΩ
- RT1 = 5.23 KΩ
- RT2 = 30.9 KΩ

8.3.6.5 Boost Mode Thermistor Monitor during Battery Discharge Mode

For battery protection during boost mode, the device monitors the battery temperature to be within the V_{BCOLD} to V_{BHOT} thresholds. When temperature is outside of the temperature thresholds, the boost mode is suspended.

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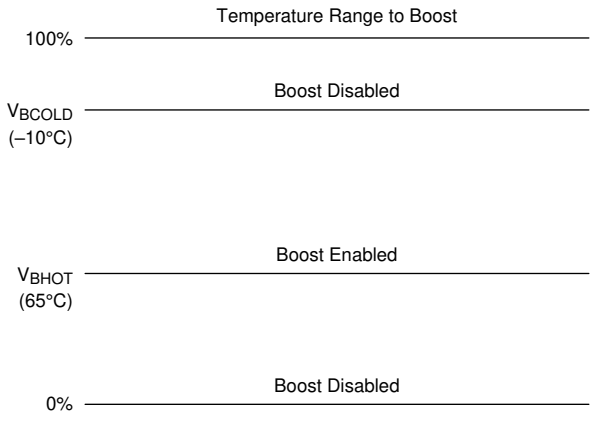


Figure 14. TS Pin Thermistor Sense Threshold in Boost Mode

8.3.6.6 Charging Safety Timer

The device has built-in safety timer to prevent extended charging cycle due to abnormal battery conditions. The safety timer is 2 hours when the battery is below $V_{BATLOWV}$ threshold and 10 hours when the battery is higher than $V_{BATLOWV}$ threshold.

During input voltage, current, JEITA cool or thermal regulation, the safety timer counts at half clock rate as the actual charge current is likely to be below the register setting. For example, if the charger is in input current regulation throughout the whole charging cycle, the safety timer will expire in 20 hours.

During the fault, timer is suspended. Once the fault goes away, fault resumes. If user stops the current charging cycle, and start again, timer gets reset.

8.3.7 Protections

8.3.7.1 Input Current Limit

The device's ILIM pin is to program maximum input current when D+/D- detection identifies an unknown adaptor plugged in. The maximum input current is set by a resistor from ILIM pin to ground as:

$$I_{INMAX} = \frac{K_{ILIM}}{R_{ILIM}} \quad (3)$$

8.3.7.2 Voltage and Current Monitoring in Converter Operation

The device closely monitors the input and system voltage, as well as internal FET currents for safe buck and boost mode operation.

8.3.7.2.1 Voltage and Current Monitoring in Buck Mode

8.3.7.2.1.1 Input Overvoltage (ACOV)

If VAC exceeds V_{VAC_OV}, HSFET stops switching immediately.

8.3.7.2.1.2 System Overvoltage Protection (SYSOVP)

The charger device clamps the system voltage during load transient so that the components connect to system would not be damaged due to high voltage. SYSOVP threshold is 350 mV above minimum system regulation voltage when the system is regulate at V_{SYS_MIN}. Upon SYSOVP, converter stops switching immediately to clamp the overshoot. The charger provides 30-mA discharge current ($I_{SYSLOAD}$) to bring down the system voltage.

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8.3.7.3 Voltage and Current Monitoring in Boost Mode

The device closely monitors the VBUS voltage, as well as RBFET and LSFET current to ensure safe boost mode operation.

8.3.7.3.1 VBUS Soft Start

When the boost function is enabled, the device soft-starts boost mode to avoid inrush current.

8.3.7.3.2 VBUS Output Protection

The device monitors boost output voltage and other conditions to provide output short circuit and overvoltage protection. The Boost build in accurate constant current regulation to allow OTG to adaptive to various types of load. If short circuit is detected on VBUS, the Boost turns off and retry 7 times. If retries are not successful, OTG is disabled.

8.3.7.3.3 Boost Mode Overvoltage Protection

When the VBUS voltage rises above regulation target and exceeds VOTG_OVP, the device stop switching.

8.3.7.4 Thermal Regulation and Thermal Shutdown

8.3.7.4.1 Thermal Protection in Buck Mode

The BQ25606 monitors the internal junction temperature T_J to avoid overheat the chip and limits the IC surface temperature in buck mode. When the internal junction temperature exceeds thermal regulation limit (110°C), the device lowers down the charge current. During thermal regulation, the actual charging current is usually below the programmed battery charging current. Therefore, termination is disabled, the safety timer runs at half the clock rate.

8.3.7.4.2 Thermal Protection in Boost Mode

The device monitors the internal junction temperature to provide thermal shutdown during boost mode. When IC junction temperature exceeds T_{SHUT} (160ºC), the boost mode is disabled and BATFET is turned off. When IC junction temperature is below T_{SHUT}(160ºC) - T_{SHUT_HYS} (30ºC), the BATFET is enabled automatically to allow system to restore .

8.3.7.5 Battery Protection

8.3.7.5.1 Battery Over-Voltage Protection (BATOVP)

The battery overvoltage limit is clamped at 4% above the battery regulation voltage. When battery over voltage occurs, the charger device immediately disables charging.

8.3.7.5.2 Battery Over-Discharge Protection

When battery is discharged below $V_{BAT_DPL_FALL}$, the BATFET is turned off to protect battery from over discharge. To recover from over-discharge latch-off, an input source plug-in is required at VBUS. The battery is charged with I_{SHORT} (typically 100 mA) current when the $V_{BAT} < V_{SHORT}$, or precharge current as set by 5% of ICHG when the battery voltage is between V_{SHORTZ} and V_{BAT_LOWV}.

8.3.7.5.3 System Over-Current Protection

When the system is shorted or significantly overloaded ($I_{BAT} > I_{BATOP}$) and the current exceeds BATFET overcurrent limit, the BATFET latches off. The BATFET latch can be reset with VBUS plug-in.

9 Application and Implementation

NOTE

information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

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9.1 Application Information

A typical application consists of the device configured as a stand-alone power path management device and a single cell battery charger for Li-Ion and Li-polymer batteries used in a wide range of smart phones and other portable devices. It integrates an input reverse-block FET (RBFET, Q1), high-side switching FET (HSFET, Q2), low-side switching FET (LSFET, Q3), and battery FET (BATFET Q4) between the system and battery. The device also integrates a bootstrap diode for the high-side gate drive.

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9.2 Typical Application

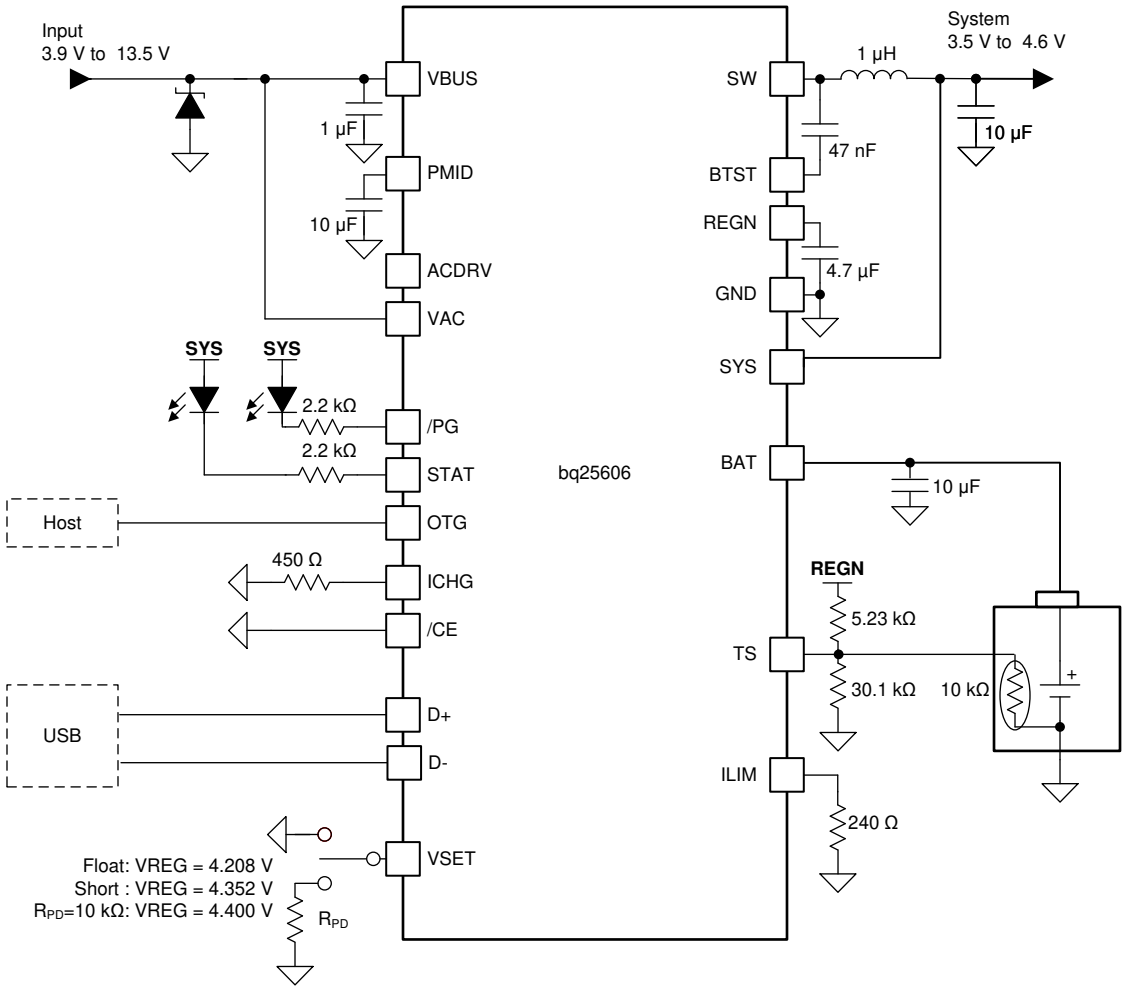


Figure 15. BQ25606 Application Diagram

9.2.1 Design Requirements

9.2.2 Detailed Design Procedure

9.2.2.1 Inductor Selection

The 1.5-MHz switching frequency allows the use of small inductor and capacitor values to maintain an inductor saturation current higher than the charging current (I_{CHG}) plus half the ripple current (I_{RIPPLE}):

$$I_{SAT} \geq I_{CHG} + (1/2)\ I_{RIPPLE} \quad (4)$$

The inductor ripple current depends on the input voltage (V_{VBUS}), the duty cycle ($D = V_{BAT}/V_{VBUS}$), the switching frequency (f_S) and the inductance (L).

$$I_{RIPPLE} = \frac{V_{IN} \times D \times (1 - D)}{fs \times L} \quad (5)$$

The maximum inductor ripple current occurs when the duty cycle (D) is 0.5 or approximately 0.5. Usually inductor ripple is designed in the range between 20% and 40% maximum charging current as a trade-off between inductor size and efficiency for a practical design.

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Typical Application (continued)

9.2.2.2 Input Capacitor

Design input capacitance to provide enough ripple current rating to absorb input switching ripple current. The worst case RMS ripple current is half of the charging current when duty cycle is 0.5. If the converter does not operate at 50% duty cycle, then the worst case capacitor RMS current I_{Cin} occurs where the duty cycle is closest to 50% and can be estimated using Equation 6.

$$I_{CIN} = I_{CHG} \times \sqrt{D \times (1 - D)} \quad (6)$$

Low ESR ceramic capacitor such as X7R or X5R is preferred for input decoupling capacitor and should be placed to the drain of the high-side MOSFET and source of the low-side MOSFET as close as possible. Voltage rating of the capacitor must be higher than normal input voltage level. A rating of 25-V or higher capacitor is preferred for 15 V input voltage. Capacitance of 22-μF is suggested for typical of 3-A charging current.

9.2.2.3 Output Capacitor

Ensure that the output capacitance has enough ripple current rating to absorb the output switching ripple current. Equation 7 shows the output capacitor RMS current I_{COUT} calculation.

$$I_{COUT} = \frac{I_{RIPPLE}}{2 \times \sqrt{3}} \approx 0.29 \times I_{RIPPLE} \quad (7)$$

The output capacitor voltage ripple can be calculated as follows:

$$\Delta V_O = \frac{V_{OUT}}{8LCfs^2}\left(1 - \frac{V_{OUT}}{V_{IN}}\right) \quad (8)$$

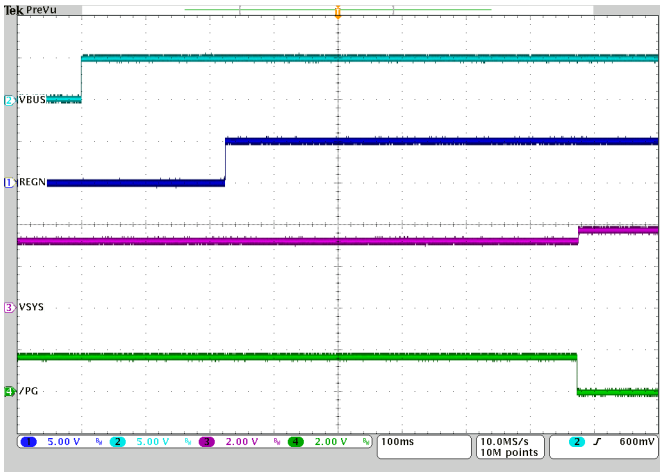
At certain input and output voltage and switching frequency, the voltage ripple can be reduced by increasing the output filter LC.

The charger device has internal loop compensation optimized for >20-μF ceramic output capacitance. The preferred ceramic capacitor is 10-V rating, X7R or X5R.

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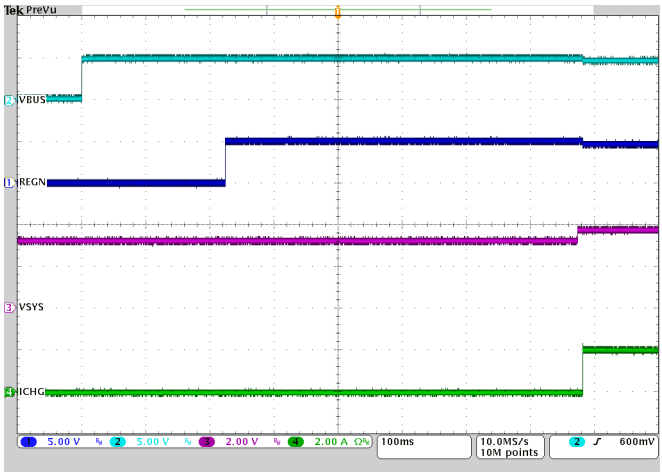
Typical Application (continued)

9.2.3 Application Curves



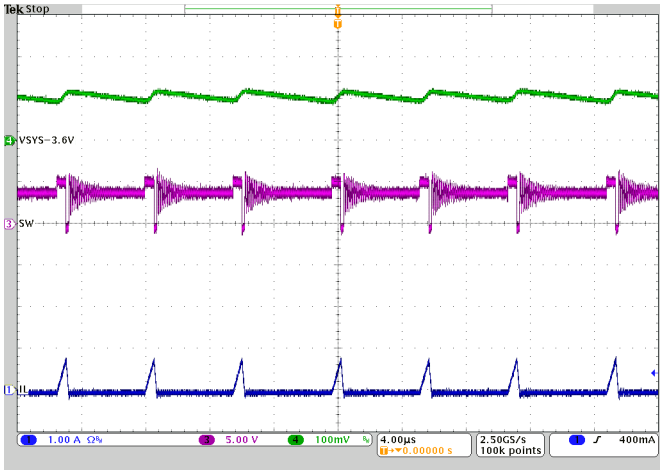
V_{VBUS} = 5 V V_{VBAT} = 3.2 V

Figure 16. Power-Up with Charge Disabled



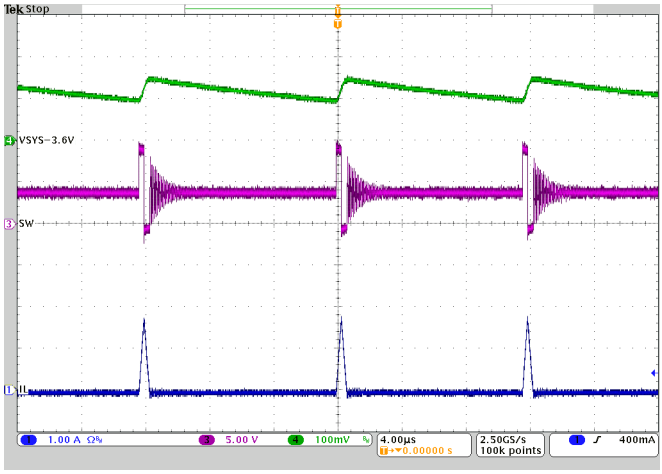
V_{VBUS} = 5 V V_{VBAT} = 3.2 V
I_{CHG} = 2 A

Figure 17. Power-Up with Charge Enabled



V_{VBUS} = 5 V
I_{SYS} = 50 mA Charge Disabled

Figure 18. PFM Switching in Buck Mode

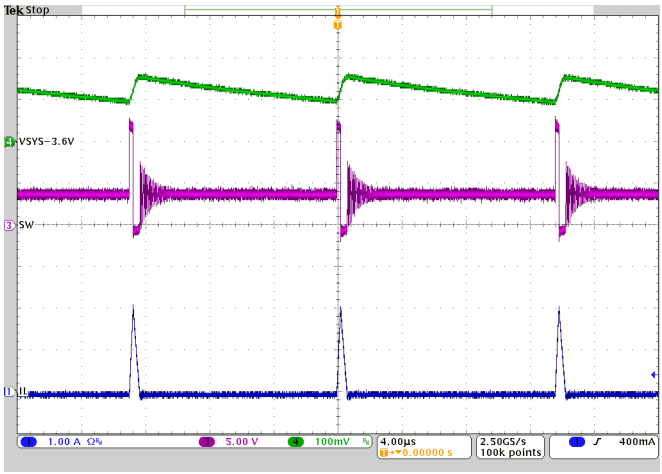


V_{VBUS} = 9 V
I_{SYS} = 50 mA Charge Disabled

Figure 19. PFM Switching in Buck Mode

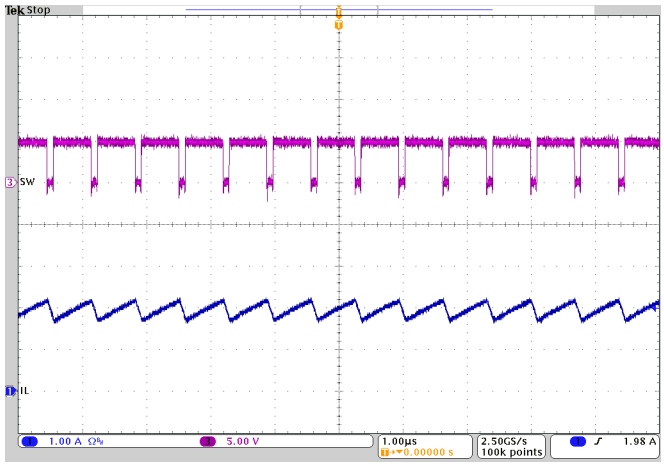
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Typical Application (continued)



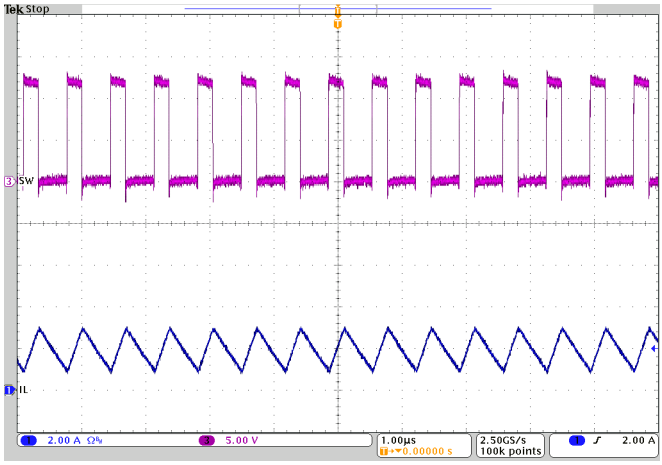
V_{VBUS} = 12 V
I_{SYS} = 50 mA
Charge Disabled

Figure 20. PFM Switching in Buck Mode



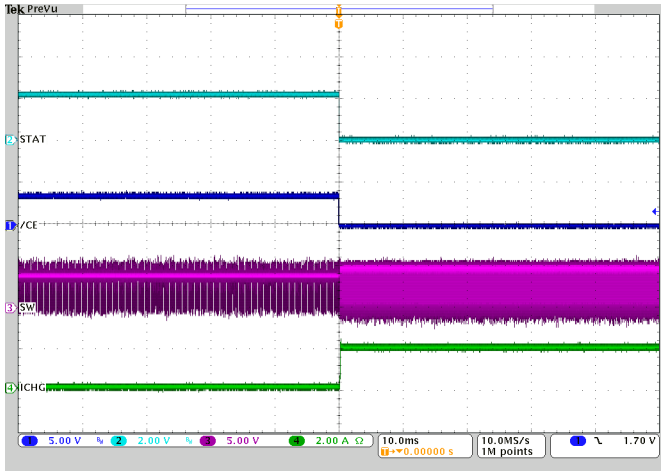
V_{VBUS} = 5 V
I_{CHG} = 2 A
V_{VBAT} = 3.8 V

Figure 21. PWM Switching in Buck Mode



V_{VBUS} = 12 V
I_{CHG} = 2 A
V_{VBAT} = 3.8 V

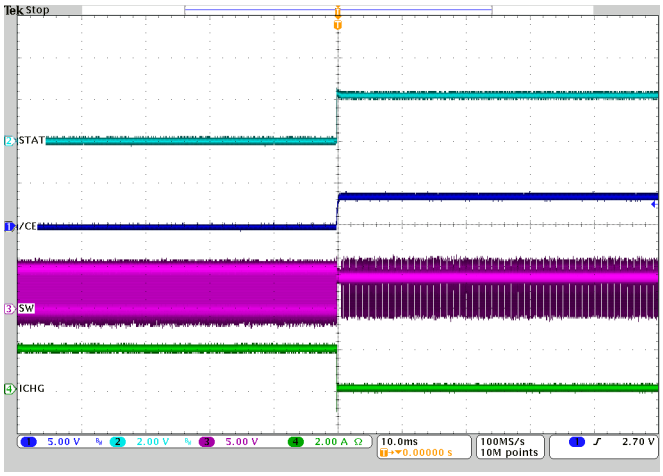
Figure 22. PWM Switching in Buck mode



V_{VBUS} = 5 V
I_{CHG} = 2 A
V_{VBAT} = 3.2 V

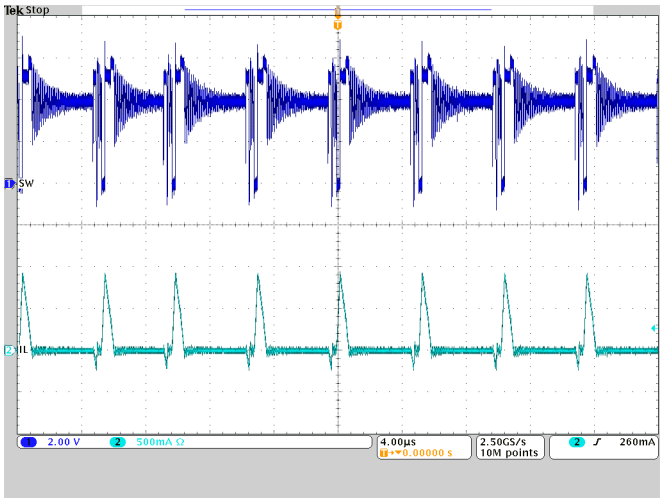
Figure 23. Charge Enable

Typical Application (continued)



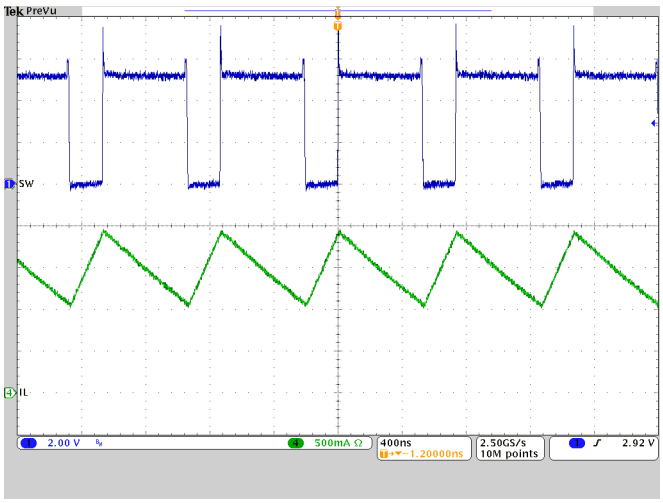
V_{VBUS} = 5 V V_{VBAT} = 3.2 V
I_{CHG} = 2 A

Figure 24. Charge Disable



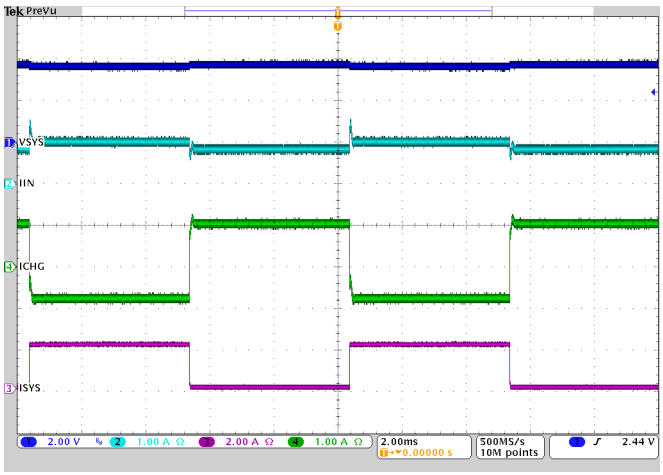
V_{VBAT} = 4 V
I_{LOAD}= 50 mA PFM Enabled

Figure 25. OTG Switching



V_{VBAT} = 4 V
I_{LOAD}= 1 A PFM Enabled

Figure 26. OTG Switching

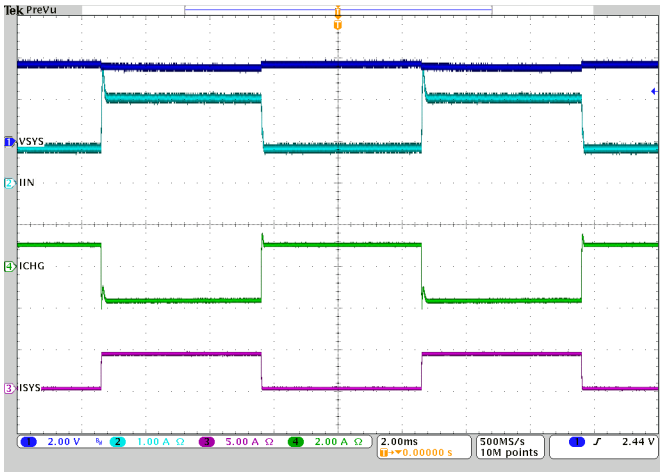


V_{VBUS} = 5 V I_{INDPM} = 1 A
I_{SYS} from 0 A to 2 A I_{CHG} = 1 A
V_{BAT} = 3.7 V

Figure 27. System Load Transient

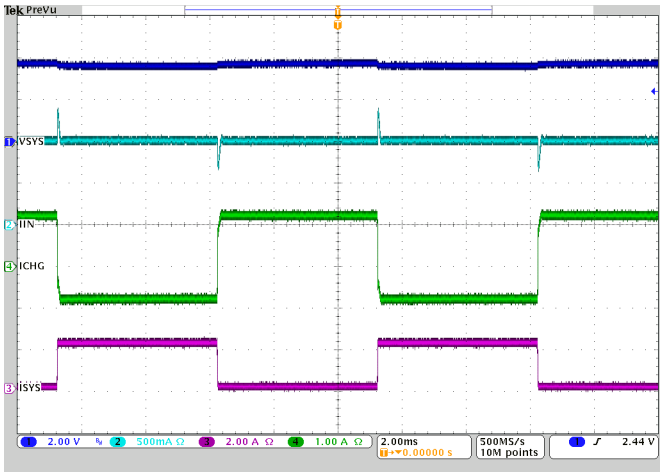
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Typical Application (continued)



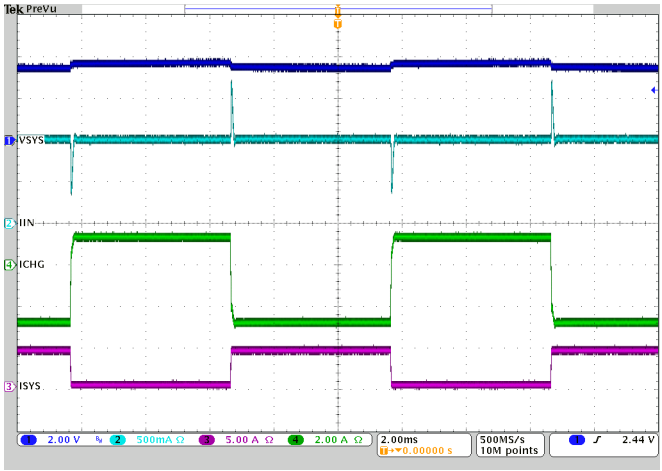
V_{VBUS} = 5 V
I_{SYS} from 0 A to 4 A
V_{BAT} = 3.7 V
I_{INDPM} = 2 A
I_{CHG} = 1 A

Figure 28. System Load Transient



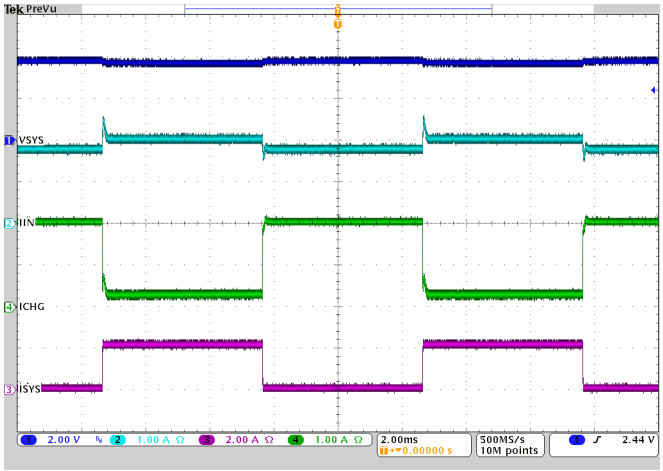
V_{VBUS} = 5 V
I_{SYS} from 0 A to 2 A
V_{BAT} = 3.7 V
I_{INDPM} = 1 A
I_{CHG} = 2 A

Figure 29. System Load Transient



V_{VBUS} = 5 V
I_{SYS} from 0 A to 4 A
V_{BAT} = 3.7 V
I_{INDPM} = 1 A
I_{CHG} = 2 A

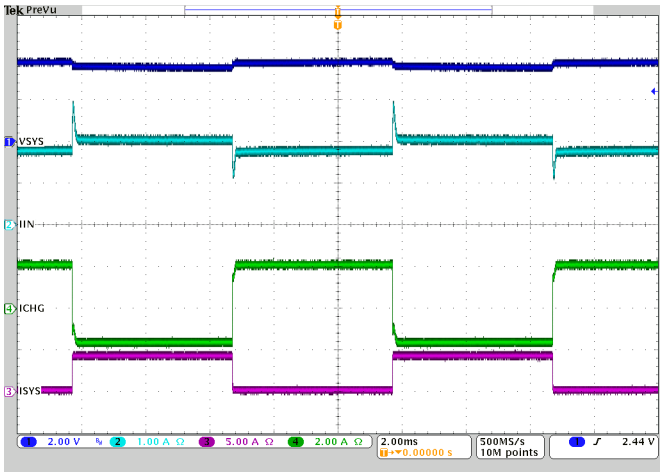
Figure 30. System Load Transient



V_{VBUS} = 5 V
I_{SYS} from 0 A to 2 A
V_{BAT} = 3.7 V
I_{INDPM} = 2 A
I_{CHG} = 2 A

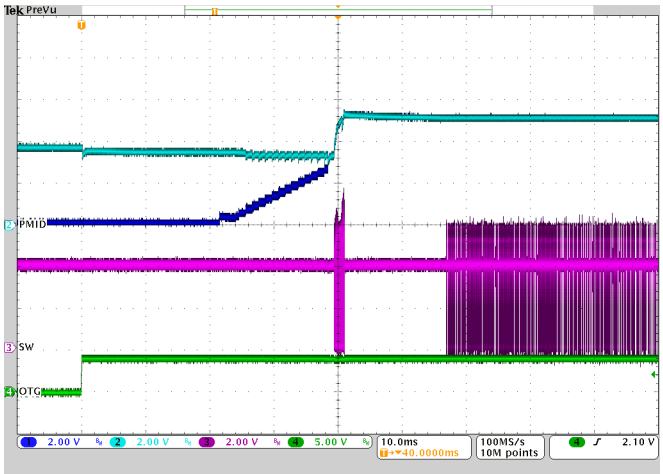
Figure 31. System Load Transient

Typical Application (continued)



V_{VBUS} = 5 V
I_{SYS} from 0 A to 4 A
V_{BAT} = 3.7 V
I_{INDPM} = 2 A
I_{CHG} = 2 A

Figure 32. System Load Transient



V_{BAT} = 3.8 V
C_{LOAD} = 470 µF

Figure 33. OTG Start-Up

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10 Power Supply Recommendations

In order to provide an output voltage on SYS, the BQ25606 device requires a power supply between 3.9 V and 13.5 V input with at least 100-mA current rating connected to VBUS and a single-cell Li-Ion battery with voltage > $V_{BATUVLO}$ connected to BAT. The source current rating needs to be at least 3 A in order for the buck converter of the charger to provide maximum output power to SYS.

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11 Layout

11.1 Layout Guidelines

The switching node rise and fall times should be minimized for minimum switching loss. Proper layout of the components to minimize high frequency current path loop (see Figure 34) is important to prevent electrical and magnetic field radiation and high frequency resonant problems. Follow this specific order carefully to achieve the proper layout.

1. Place input capacitor as close as possible to PMID pin and GND pin connections and use shortest copper trace connection or GND plane.
2. Place inductor input pin to SW pin as close as possible. Minimize the copper area of this trace to lower electrical and magnetic field radiation but make the trace wide enough to carry the charging current. Do not use multiple layers in parallel for this connection. Minimize parasitic capacitance from this area to any other trace or plane.
3. Put output capacitor near to the inductor and the device. Ground connections need to be tied to the IC ground with a short copper trace connection or GND plane.
4. Route analog ground separately from power ground. Connect analog ground and connect power ground separately. Connect analog ground and power ground together using thermal pad as the single ground connection point. Or using a 0-Ω resistor to tie analog ground to power ground.
5. Use single ground connection to tie charger power ground to charger analog ground. Just beneath the device. Use ground copper pour but avoid power pins to reduce inductive and capacitive noise coupling.
6. Place decoupling capacitors next to the IC pins and make trace connection as short as possible.
7. It is critical that the exposed thermal pad on the backside of the device package be soldered to the PCB ground. Ensure that there are sufficient thermal vias directly under the IC, connecting to the ground plane on the other layers.
8. Ensure that the number and sizes of vias allow enough copper for a given current path.

Refer to the *BQ25601 and BQ25601D (PWR877) Evaluation Module User's Guide* for the recommended component placement with trace and via locations. For the VQFN information, refer to the *Quad Flatpack No-Lead Logic Packages Application Report* and *QFN and SON PCB Attachment Application Report*.

11.2 Layout Example

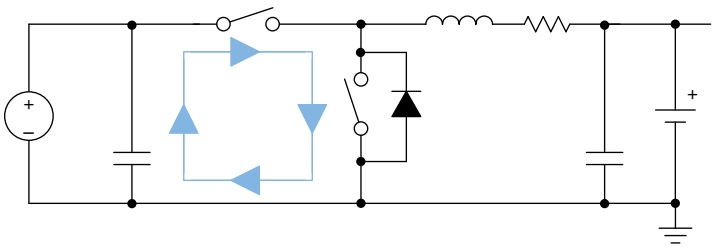


Figure 34. High Frequency Current Path

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Layout Example (continued)

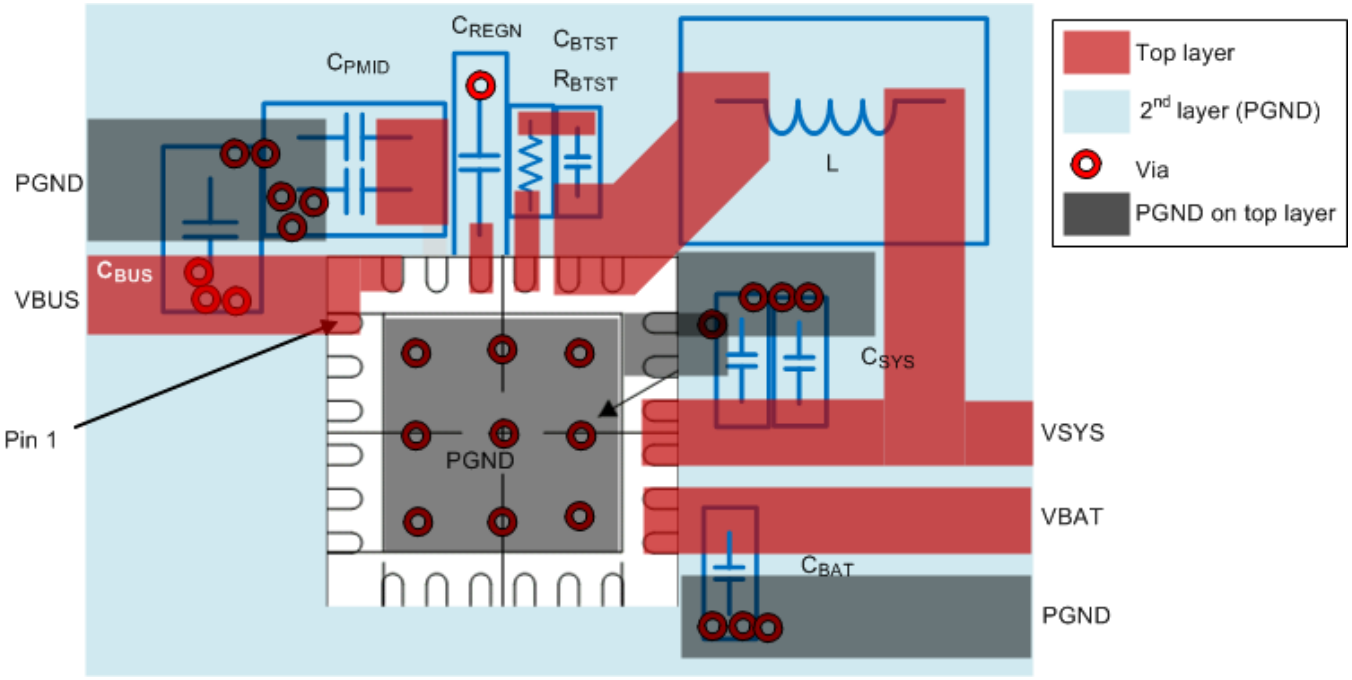


Figure 35. Layout Example

12 Device and Documentation Support

12.1 Device Support

12.1.1 Third-Party Products Disclaimer

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12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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12.4 Trademarks

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12.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

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13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ25606RGER	ACTIVE	VQFN	RGE	24	3000	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BQ25606	Samples
BQ25606RGET	ACTIVE	VQFN	RGE	24	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BQ25606	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

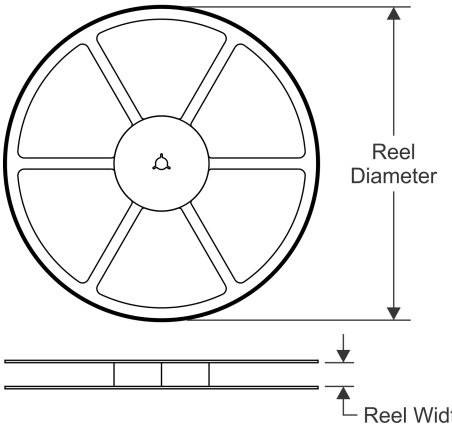
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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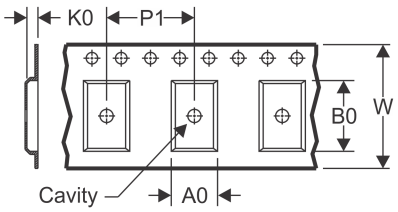
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

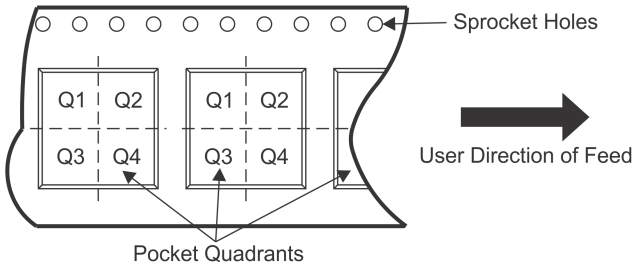


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

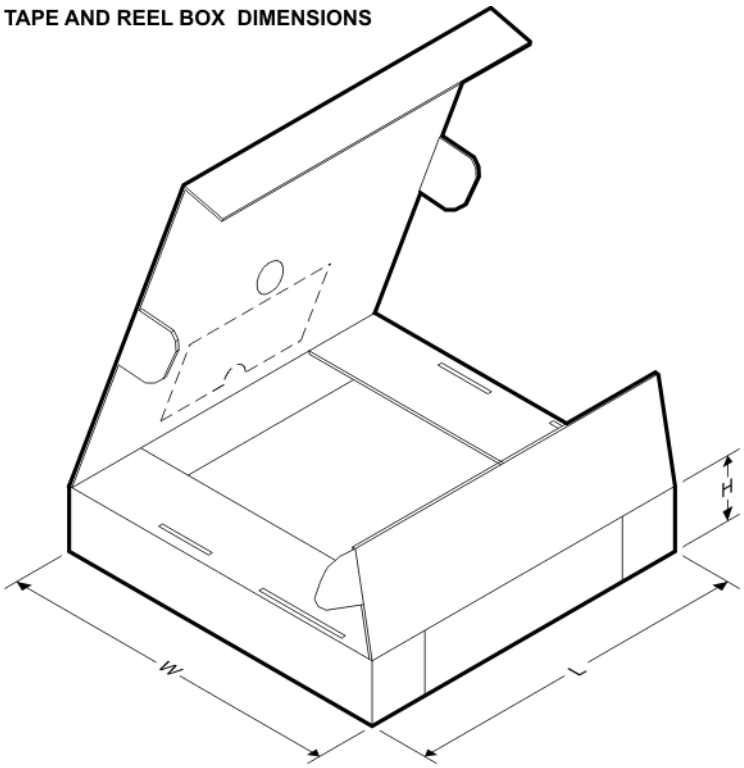
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ25606RGER	VQFN	RGE	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
BQ25606RGET	VQFN	RGE	24	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



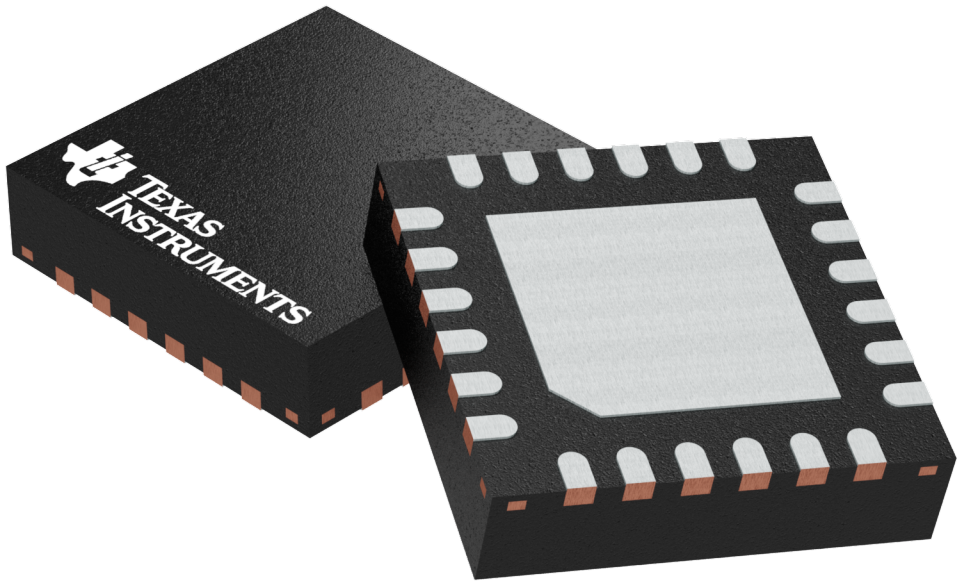
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ25606RGER	VQFN	RGE	24	3000	367.0	367.0	35.0
BQ25606RGET	VQFN	RGE	24	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

RGE 24 VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

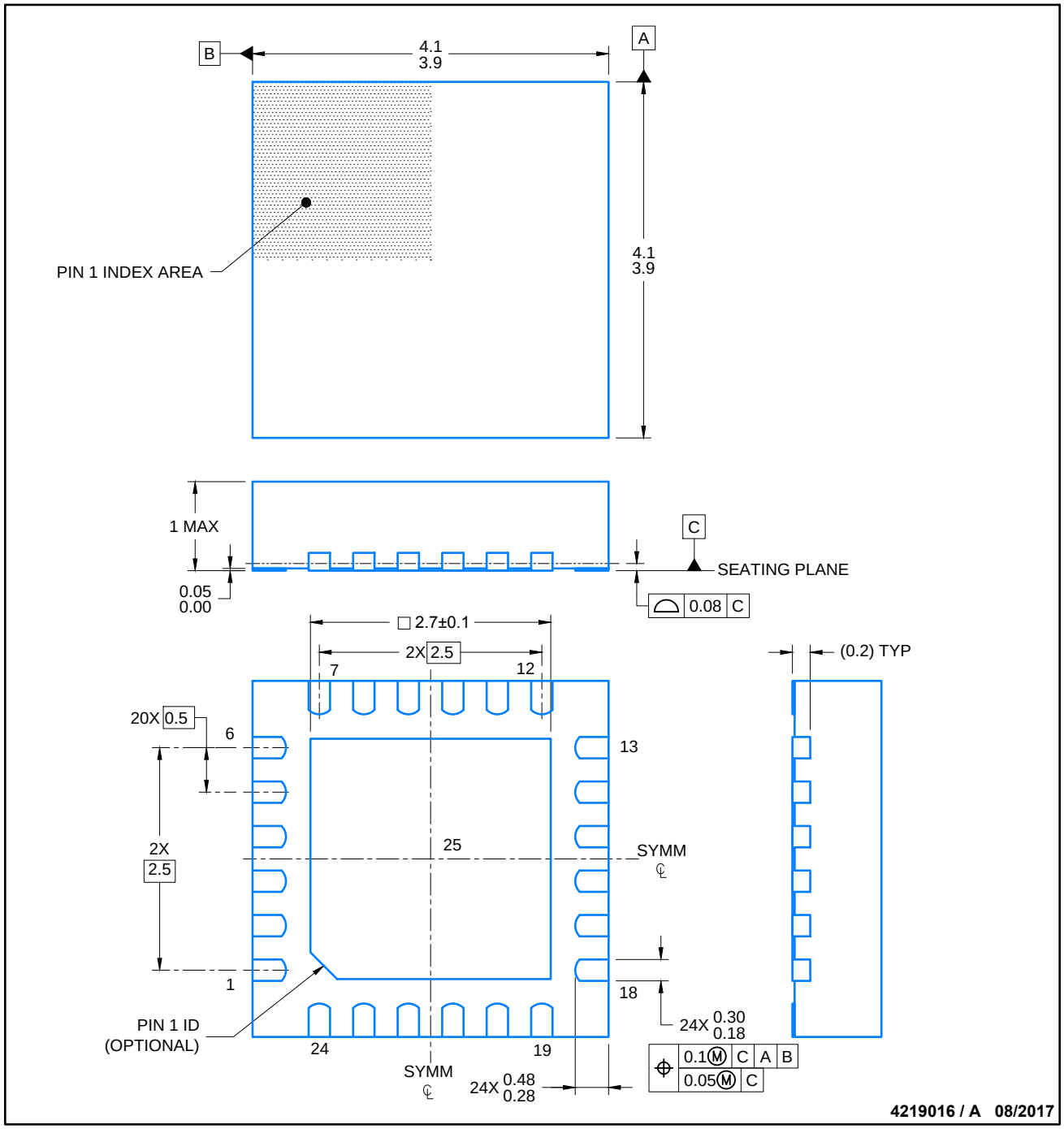
4204104/H

PACKAGE OUTLINE

RGE0024H

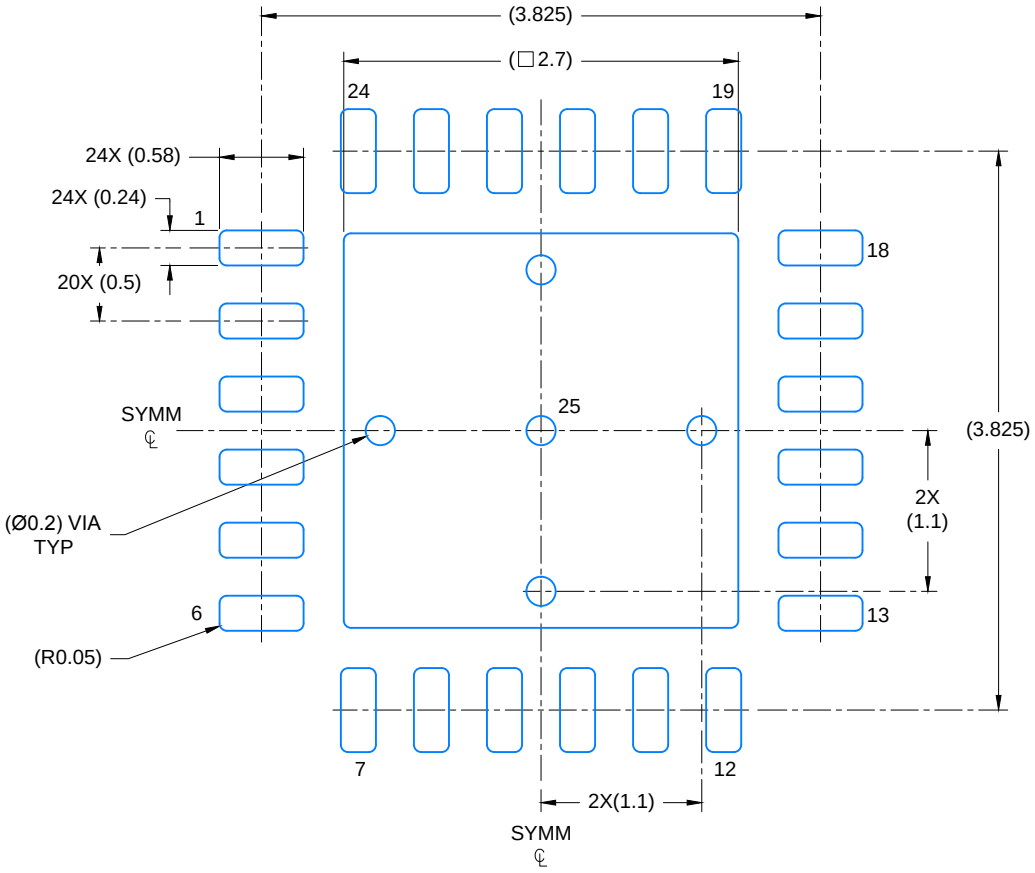
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK- NO LEAD



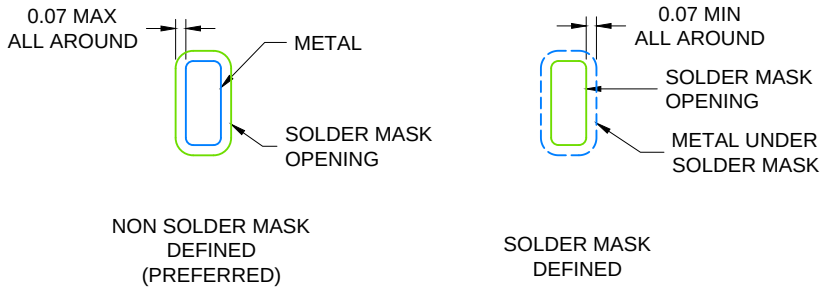
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE

SCALE: 20X

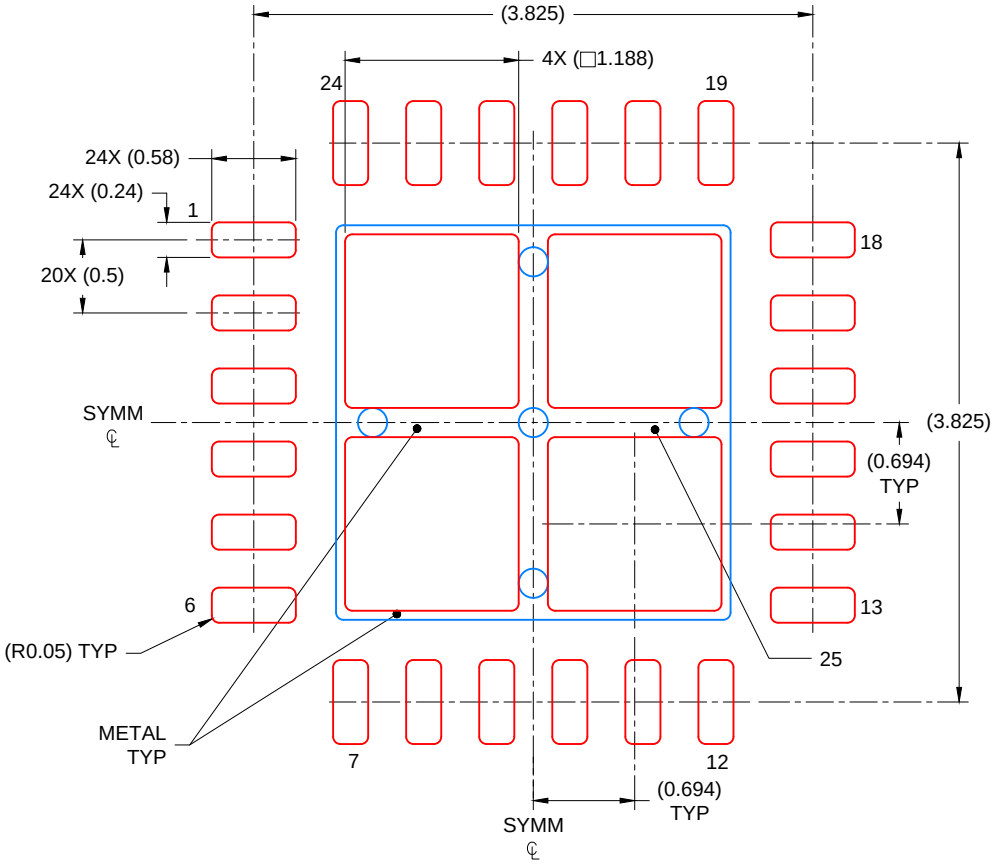


SOLDER MASK DETAILS

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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
78% PRINTED COVERAGE BY AREA
SCALE: 20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations..

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